

MOS INTEGRATED CIRCUIT

μ PD70F3038, 70F3038Y, 70F3040, 70F3040Y

V850/SV1™

32-BIT SINGLE-CHIP MICROCONTROLLERS

DESCRIPTION

The μ PD70F3038, μ PD70F3038Y, μ PD70F3040, and μ PD70F3040Y are products that substitute flash memory for the mask ROM of the μ PD703038, μ PD703038Y, μ PD703039, 703040, and 703041, and μ PD703039Y, 703040Y, and 703041Y, respectively. Since the μ PD70F3038, μ PD70F3038Y, μ PD70F3040, and μ PD70F3040Y can be read and written while mounted on the board, these products are ideal for evaluation during system development, multiple-version small-scale production or quick product release.

Detailed function descriptions are provided in the following user's manuals. Be sure to read them before designing.

V850/SV1 User's Manual Hardware: U14462E
 V850 Family™ User's Manual Architecture: U10243E

FEATURES

- ★ ○ Pin compatible with μ PD703038, 703039, 703040, 703041, 703038Y, 703039Y, 703040Y, and 703041Y
 - For mass production, these can be replaced by a mask ROM version.
 - μ PD70F3038F1-EN2 → μ PD703038F1-xxx-EN2
 - μ PD70F3038YF1-EN2 → μ PD703038YF1-xxx-EN2
 - μ PD70F3040GM-UEU → μ PD703039GM-xxx-UEU, 703040GM-xxx-UEU, 703041GM-xxx-UEU
 - μ PD70F3040F1-EN2 → μ PD703039F1-xxx-EN2, 703040F1-xxx-EN2
 - μ PD70F3040YGM-UEU → μ PD703039YGM-xxx-UEU, 703040YGM-xxx-UEU, 703041YGM-xxx-UEU
 - μ PD70F3040YF1-EN2 → μ PD703039YF1-xxx-EN2, 703040YF1-xxx-EN2

★ APPLICATIONS

- Camcorders (including DVC)

★ ORDERING INFORMATION

Part Number	Package
μ PD70F3038F1-EN2	180-pin plastic FBGA (13 × 13)
μ PD70F3038YF1-EN2	180-pin plastic FBGA (13 × 13)
μ PD70F3040GM-UEU	176-pin plastic LQFP (fine pitch) (24 × 24)
μ PD70F3040F1-EN2	180-pin plastic FBGA (13 × 13)
μ PD70F3040YGM-UEU	176-pin plastic LQFP (fine pitch) (24 × 24)
μ PD70F3040YF1-EN2	180-pin plastic FBGA (13 × 13)

The information in this document is subject to change without notice. Before using this document, please confirm that this is the latest version.
 Not all devices/types available in every country. Please check with local NEC representative for availability and additional information.

DIFFERENCES BETWEEN V850/SV1 PRODUCTS

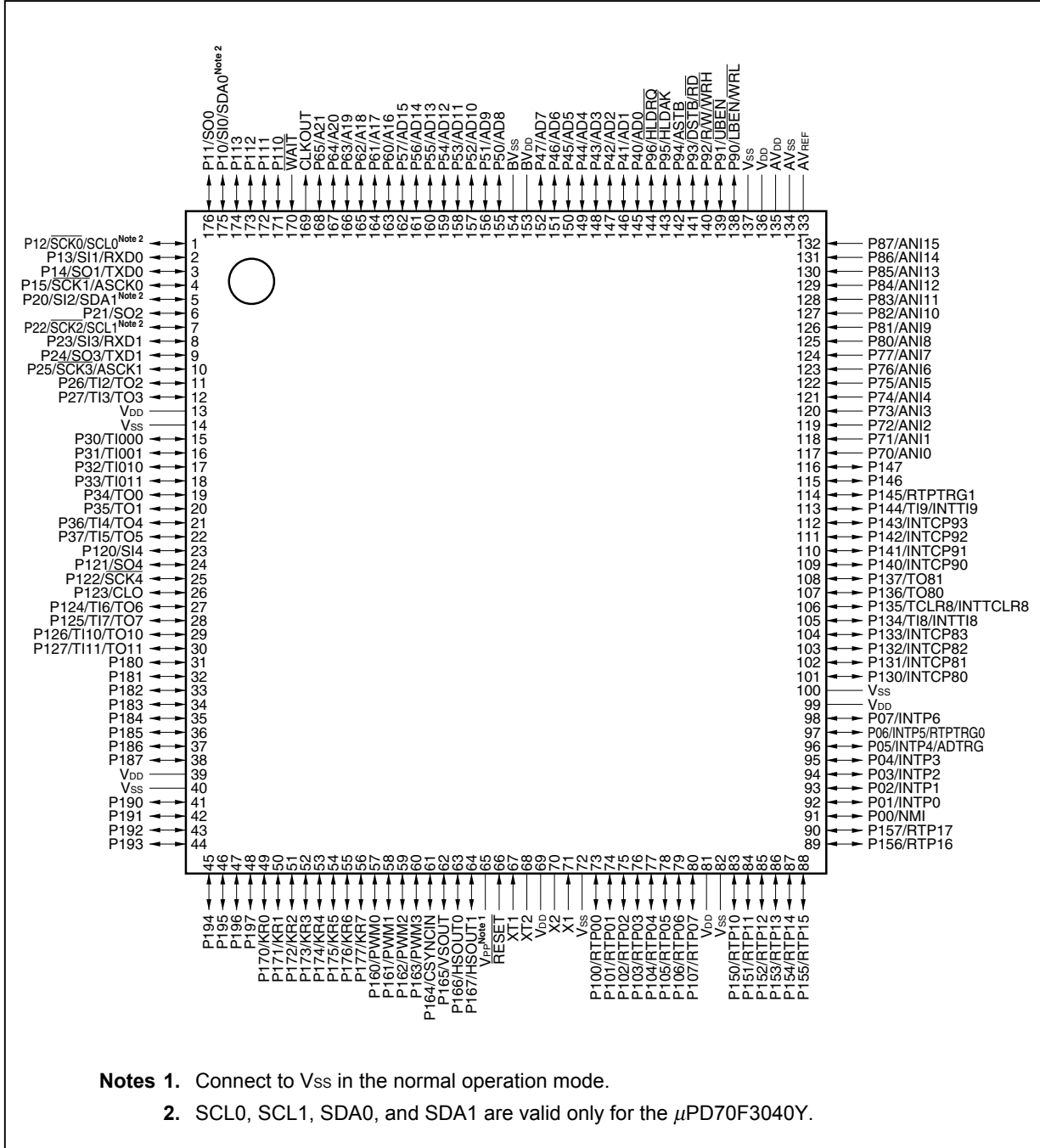
	Internal ROM	Internal RAM	I ² C	V _{PP} Pin
★ μPD70F3038	384 KB (flash memory)	16 KB	None	Provided
★ μPD70F3038Y			Provided	
μPD70F3040	256 KB (flash memory)	16 KB	None	
μPD70F3040Y			Provided	
★ μPD703038	384 KB (mask ROM)	16 KB	None	None
★ μPD703038Y			Provided	
μPD703039	256 KB (mask ROM)	8 KB	None	
μPD703039Y			Provided	
μPD703040		16 KB	None	
μPD703040Y			Provided	
μPD703041	192 KB (mask ROM)	8 KB	None	
μPD703041Y			Provided	

PIN CONFIGURATION

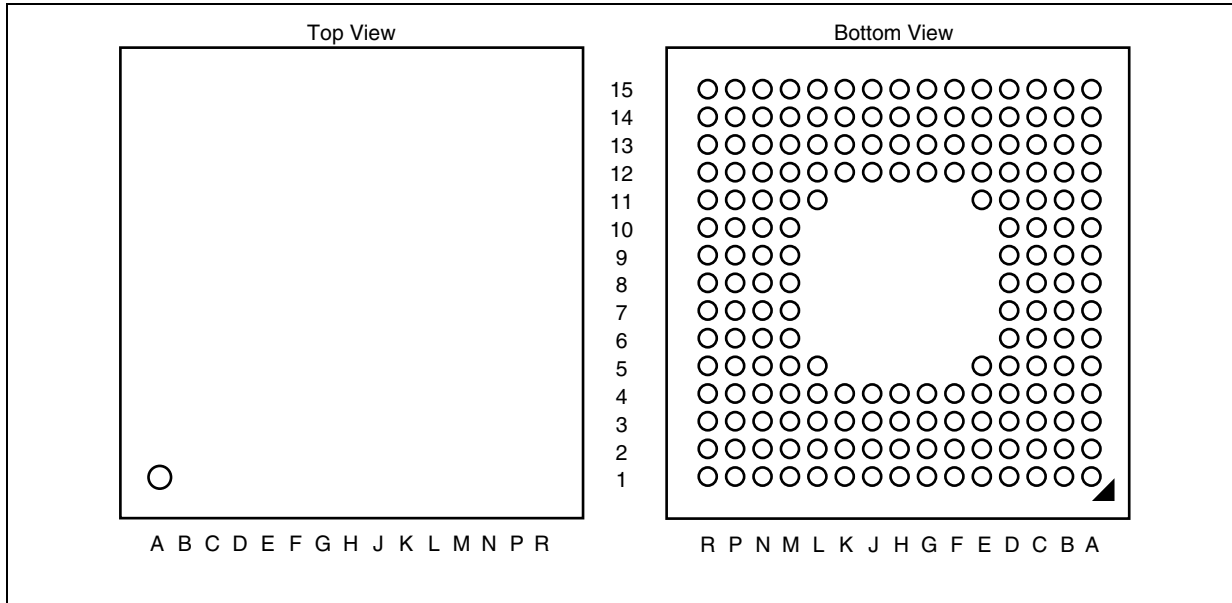
176-pin plastic LQFP (fine pitch) (24 × 24)

μPD70F3040GM-UEU

μPD70F3040YGM-UEU



- ★ 180-pin plastic FBGA (13 × 13)
 - μ PD70F3038F1-EN2
 - μ PD70F3038YF1-EN2
 - μ PD70F3040F1-EN2
 - μ PD70F3040YF1-EN2



Pin Number	Name	Pin Number	Name	Pin Number	Name	Pin Number	Name
A1	NC ^{Note 1}	B1	P13/SI1/RXD0	C1	P15/SCK1/ASCK0	D1	P23/SI3/RXD1
A2	P11/SO0	B2	P12/SCK0/SCL0 ^{Note 2}	C2	P20/SI2/SDA1 ^{Note 2}	D2	P21/SO2
A3	P10/SI0/SDA0 ^{Note 2}	B3	P113	C3	P14/SO1/TXD0	D3	P22/SCK2/SCL1 ^{Note 2}
A4	P112	B4	P110	C4	P111	D4	P24/SO3/TXD1
A5	CLKOUT	B5	P64/A20	C5	P65/A21	D5	WAIT
A6	P62/A18	B6	P60/A16	C6	P63/A19	D6	P61/A17
A7	P57/AD15	B7	P54/AD12	C7	P56/AD14	D7	P55/AD13
A8	P53/AD11	B8	P50/AD8	C8	P52/AD10	D8	P51/AD9
A9	BV _{SS}	B9	P46/AD6	C9	BV _{DD}	D9	P47/AD7
A10	P45/AD5	B10	P42/AD2	C10	P44/AD4	D10	P43/AD3
A11	P41/AD1	B11	P94/ASTB	C11	P40/AD0	D11	P96/HLDRQ
A12	V _{SS}	B12	P91/UBEN	C12	P93/DSTB/RD	D12	P90/LBEN/WRL
A13	AV _{SS}	B13	AV _{DD}	C13	P82/ANI10	D13	P81/ANI9
A14	AV _{REF}	B14	V _{DD}	C14	P86/ANI14	D14	P84/ANI12
A15	NC ^{Note 1}	B15	P87/ANI15	C15	P85/ANI13	D15	P83/ANI11

- Notes**
1. Leave the NC pin open.
 2. SCL0, SCL1, SDA0, and SDA1 are valid only for the μPD70F3038Y and 70F3040Y.

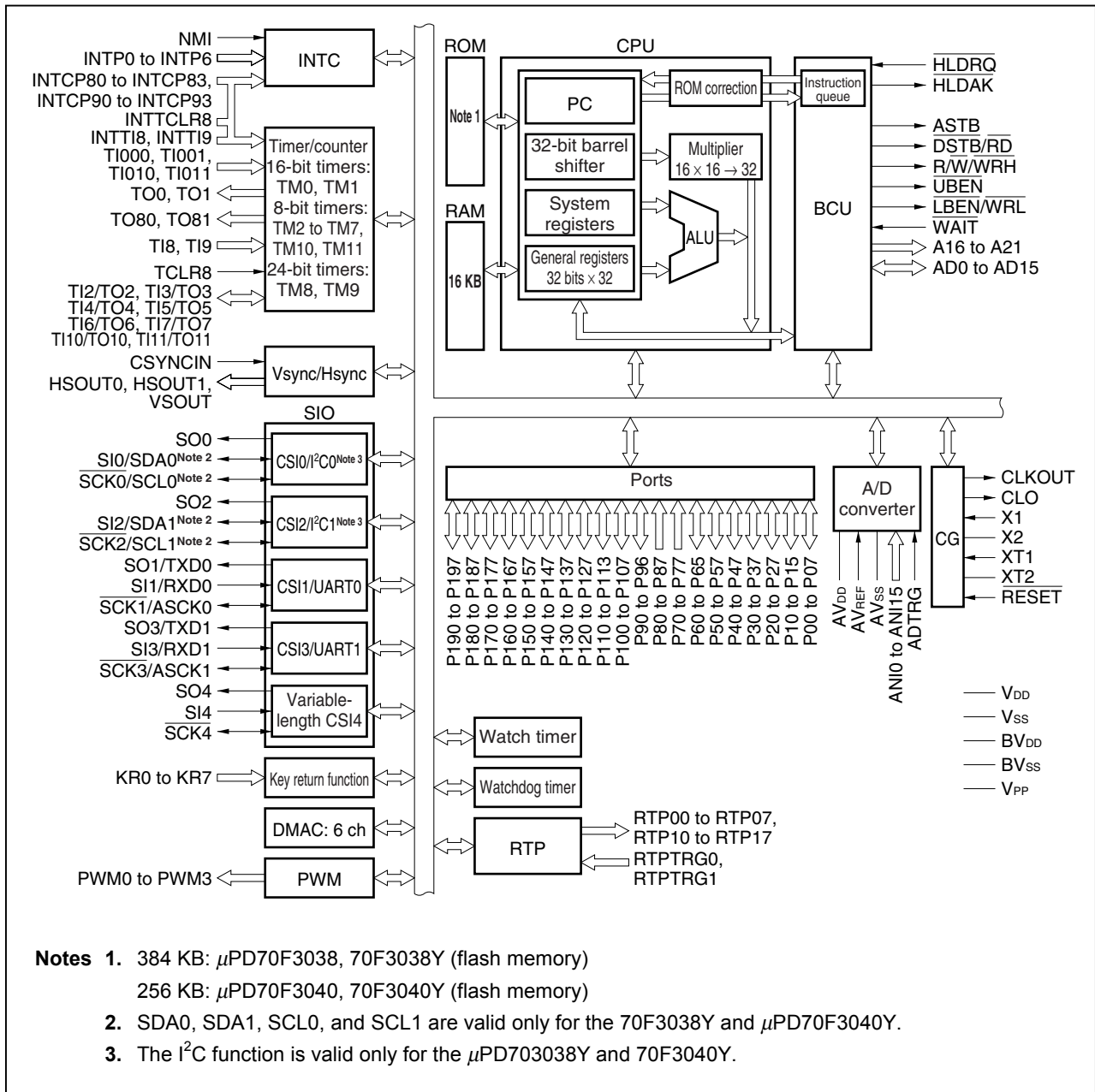
Pin Number	Name	Pin Number	Name	Pin Number	Name	Pin Number	Name
E1	P27/TI3/TO3	H12	P144/TI9/INTTI9	M1	V _{DD}	P1	P193
E2	P25/SCK3/ASCK1	H13	P143/INTCP93	M2	P186	P2	P195
E3	P26/TI2/TO2	H14	P146	M3	P170/KR0	P3	P196
E4	V _{SS}	H15	P141/INTCP91	M4	P174/KR4	P4	P176/KR6
E5	V _{DD}	J1	P125/TI7/TO7	M5	P177/KR7	P5	P160/PWM0
E11	P95/HLDAK	J2	P124/TI6/TO6	M6	P163/PWM3	P6	P164/CSYNCIN
E12	P92/RW/WRH	J3	P126/TI10/TO10	M7	P167/HSOUT1	P7	V _{PP} ^{Note 1}
E13	P76/ANI6	J4	P127/TI11/TO11	M8	RESET	P8	X2
E14	P77/ANI7	J12	P140/INTCP90	M9	V _{SS}	P9	P100/RTP00
E15	P80/ANI8	J13	P137/TO81	M10	P103/RTP03	P10	P104/RTP04
F1	P30/TI000	J14	P142/INTCP92	M11	P01/INTP0	P11	P107/RTP07
F2	P31/TI001	J15	P135/TCLR8/INTTCLR8	M12	P04/INTP3	P12	P150/RTP10
F3	P32/TI010	K1	P181	M13	P05/INTP4/ADTRG	P13	P152/RTP12
F4	P33/TI011	K2	P180	M14	P03/INTP2	P14	P153/RTP13
F12	P74/ANI4	K3	P182	M15	P06/INTP5/RTPTRG0	P15	P156/RTP16
F13	P72/ANI2	K4	P183	N1	P191	R1	NC ^{Note 2}
F14	P75/ANI5	K12	P134/TI8/INTTI8	N2	P192	R2	P194
F15	P70/ANI0	K13	P133/INTCP83	N3	P197	R3	P171/KR1
G1	P35/TO1	K14	P136/TO80	N4	P173/KR3	R4	P172/KR2
G2	P34/TO0	K15	P132/INTCP82	N5	P175/KR5	R5	P161/PWM1
G3	P36/TI4/TO4	L1	P185	N6	P162/PWM2	R6	P165/VSOUT
G4	P37/TI5/TO5	L2	P184	N7	P166/HSOUT0	R7	XT1
G12	P73/ANI3	L3	P187	N8	V _{DD}	R8	XT2
G13	P147	L4	V _{SS}	N9	X1	R9	P101/RTP01
G14	P71/ANI1	L5	P190	N10	P102/RTP02	R10	P105/RTP05
G15	P145/RTPTRG1	L11	V _{DD}	N11	P106/RTP06	R11	V _{SS}
H1	P121/SO4	L12	V _{SS}	N12	V _{DD}	R12	P151/RTP11
H2	P120/SI4	L13	P07/INTP6	N13	P157/RTP17	R13	P154/RTP14
H3	P122/SCK4	L14	P131/INTCP81	N14	P00/NMI	R14	P155/RTP15
H4	P123/CLO	L15	P130/INTCP80	N15	P02/INTP1	R15	NC ^{Note 2}

- Notes**
1. Connect this pin to V_{SS} during normal operation mode.
 2. Leave the NC pin open.

PIN IDENTIFICATION

A16 to A21:	Address bus	P120 to P127:	Port 12
AD0 to AD15:	Address/data bus	P130 to P137:	Port 13
ADTRG:	AD trigger input	P140 to P147:	Port 14
ANI0 to ANI15:	Analog input	P150 to P157:	Port 15
ASCK0, ASCK1:	Asynchronous serial clock	P160 to P167:	Port 16
ASTB:	Address strobe	P170 to P177:	Port 17
AV _{DD} :	Analog power supply	P180 to P187:	Port 18
AV _{REF} :	Analog reference voltage	P190 to P197:	Port 19
AV _{SS} :	Analog ground	PWM0 to PWM3:	Pulse width modulation
BV _{DD} :	Bus interface power supply	\overline{RD} :	Read
BV _{SS} :	Bus interface ground	\overline{RESET} :	Reset
CLKOUT:	Clock output	RTP00 to RTP07,:	Real-time output port
CLO:	Clock output (divided)	RTP10 to RTP17	
CSYNCIN:	Csync input	RTPTRG0, RTPTRG1:	RTP trigger input
\overline{DSTB} :	Data strobe	R \overline{W} :	Read/write status
H \overline{LDAK} :	Hold acknowledge	RXD0, RXD1:	Receive data
H \overline{LDRQ} :	Hold request	$\overline{SCK0}$ to $\overline{SCK4}$:	Serial clock
HSOUT0, HSOUT1:	Hsync output	SCL0, SCL1:	Serial clock
INTCP80 to INTCP83,:	Interrupt request from peripherals	SDA0, SDA1:	Serial data
INTCP90 to INTCP93,		SI0 to SI4:	Serial input
INTP0 to INTP6,		SO0 to SO4:	Serial output
INTTCLR8,		TCLR8:	Timer clear
INTTI8, INTTI9		TI000, TI001, TI010,:	Timer input
KR0 to KR7:	Key return	TI011, TI2 to TI11	
\overline{LBEN} :	Lower byte enable	TO0 to TO7, TO80,:	Timer output
NMI:	Non-maskable interrupt request	TO81, TO10, TO11	
P00 to P07:	Port 0	TXD0, TXD1:	Transmit data
P10 to P15:	Port 1	\overline{UBEN} :	Upper byte enable
P20 to P27:	Port 2	V _{DD} :	Power supply
P30 to P37:	Port 3	V _{PP} :	Programming power supply
P40 to P47:	Port 4	VSOUT:	Vsync output
P50 to P57:	Port 5	V _{SS} :	Ground
P60 to P65:	Port 6	\overline{WAIT} :	Wait
P70 to P77:	Port 7	\overline{WRH} :	Write strobe high level data
P80 to P87:	Port 8	\overline{WRL} :	Write strobe low level data
P90 to P96:	Port 9	X1, X2:	Crystal for main system clock
P100 to P107:	Port 10	XT1, XT2:	Crystal for subsystem clock
P110 to P113:	Port 11		

INTERNAL BLOCK DIAGRAM



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1. PIN FUNCTIONS

1.1 Port Pins

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Pin Name	I/O	PULL	Function	Alternate Function
P00	I/O	Yes	Port 0 8-bit I/O port Input/output mode can be specified in 1-bit units.	NMI
P01				INTP0
P02				INTP1
P03				INTP2
P04				INTP3
P05				INTP4/ADTRG
P06				INTP5/RTPTRG0
P07				INTP6
P10	I/O	Yes	Port 1 6-bit I/O port Input/output mode can be specified in 1-bit units.	SI0/SDA0
P11				SO0
P12				$\overline{\text{SCK0/SCL0}}$
P13				SI1/RXD0
P14				SO1/TXD0
P15				$\overline{\text{SCK1/ASCK0}}$
P20	I/O	Yes	Port 2 8-bit I/O port Input/output mode can be specified in 1-bit units.	SI2/SDA1
P21				SO2
P22				$\overline{\text{SCK2/SCL1}}$
P23				SI3/RXD1
P24				SO3/TXD1
P25				$\overline{\text{SCK3/ASCK1}}$
P26				TI2/TO2
P27				TI3/TO3
P30	I/O	Yes	Port 3 8-bit I/O port Input/output mode can be specified in 1-bit units.	TI000
P31				TI001
P32				TI010
P33				TI011
P34				TO0
P35				TO1
P36				TI4/TO4
P37				TI5/TO5
P40	I/O	No	Port 4 8-bit I/O port Input/output mode can be specified in 1-bit units.	AD0
P41				AD1
P42				AD2
P43				AD3
P44				AD4

Remark PULL: On-chip pull-up resistor

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Pin Name	I/O	PULL	Function	Alternate Function
P45	I/O	No	Port 4 8-bit I/O port Input/output mode can be specified in 1-bit units.	AD5
P46				AD6
P47				AD7
P50	I/O	No	Port 5 8-bit I/O port Input/output mode can be specified in 1-bit units.	AD8
P51				AD9
P52				AD10
P53				AD11
P54				AD12
P55				AD13
P56				AD14
P57				AD15
P60				I/O
P61	A17			
P62	A18			
P63	A19			
P64	A20			
P65	A21			
P70	Input	No	Port 7 8-bit input port	ANI0
P71				ANI1
P72				ANI2
P73				ANI3
P74				ANI4
P75				ANI5
P76				ANI6
P77				ANI7
P80	Input	No	Port 8 8-bit input port	ANI8
P81				ANI9
P82				ANI10
P83				ANI11
P84				ANI12
P85				ANI13
P86				ANI14
P87				ANI15
P90	I/O	No	Port 9 7-bit I/O port Input/output mode can be specified in 1-bit units.	$\overline{\text{LBEN}}/\overline{\text{WRL}}$
P91				$\overline{\text{UBEN}}$
P92				$\overline{\text{R/W}}/\overline{\text{WRH}}$
P93				$\overline{\text{DSTB}}/\overline{\text{RD}}$

Remark PULL: On-chip pull-up resistor

Pin Name	I/O	PULL	Function	Alternate Function
P94	I/O	No	Port 9 7-bit I/O port Input/output mode can be specified in 1-bit units.	ASTB
P95				H $\overline{\text{LDAK}}$
P96				H $\overline{\text{LDRQ}}$
P100	I/O	Yes	Port 10 8-bit I/O port Input/output mode can be specified in 1-bit units.	RTP00
P101				RTP01
P102				RTP02
P103				RTP03
P104				RTP04
P105				RTP05
P106				RTP06
P107				RTP07
P110	I/O	No	Port 11 4-bit I/O port Input/output mode can be specified in 1-bit units.	—
P111				—
P112				—
P113				—
P120	I/O	No	Port 12 8-bit I/O port Input/output mode can be specified in 1-bit units.	SI4
P121				SO4
P122				S $\overline{\text{CK4}}$
P123				CLO
P124				TI6/TO6
P125				TI7/TO7
P126				TI10/TO10
P127				TI11/TO11
P130	I/O	No	Port 13 8-bit I/O port Input/output mode can be specified in 1-bit units.	INTCP80
P131				INTCP81
P132				INTCP82
P133				INTCP83
P134				TI8/INTTI8
P135				TCLR8/INTTCLR8
P136				TO80
P137				TO81
P140	I/O	No	Port 14 8-bit I/O port Input/output mode can be specified in 1-bit units.	INTCP90
P141				INTCP91
P142				INTCP92
P143				INTCP93
P144				TI9/INTTI9
P145				RTPTRG1
P146				—
P147				—

Remark PULL: On-chip pull-up resistor

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Pin Name	I/O	PULL	Function	Alternate Function
P150	I/O	No	Port 15 8-bit I/O port Input/output mode can be specified in 1-bit units.	RTP10
P151				RTP11
P152				RTP12
P153				RTP13
P154				RTP14
P155				RTP15
P156				RTP16
P157				RTP17
P160	I/O	No	Port 16 8-bit I/O port Input/output mode can be specified in 1-bit units.	PWM0
P161				PWM1
P162				PWM2
P163				PWM3
P164				CSYNCIN
P165				VSOUT
P166				HSOUT0
P167				HSOUT1
P170	I/O	Yes	Port 17 8-bit I/O port Input/output mode can be specified in 1-bit units.	KR0
P171				KR1
P172				KR2
P173				KR3
P174				KR4
P175				KR5
P176				KR6
P177				KR7
P180	I/O	No	Port 18 8-bit I/O port Input/output mode can be specified in 1-bit units.	–
P181				–
P182				–
P183				–
P184				–
P185				–
P186				–
P187				–
P190	I/O	No	Port 19 8-bit I/O port Input/output mode can be specified in 1-bit units.	–
P191				–
P192				–
P193				–
P194				–
P195				–
P196				–
P197				–

Remark PULL: On-chip pull-up resistor

1.2 Non-Port Pins

(1/4)

Pin Name	I/O	PULL	Function	Alternate Function
A16 to A21	Output	No	Address bus 16 to 21	P60 to P65
AD0 to AD7	I/O	No	Address/data multiplexed bus 0 to 15	P40 to P47
AD8 to AD15				P50 to P57
ADTRG	Input	Yes	A/D converter external trigger input	P05/INTP4
ANI0 to ANI7	Input	No	Analog input to A/D converter	P70 to P77
ANI8 to ANI15	Input	No		P80 to P87
ASCK0	Input	Yes	Baud rate clock input for UART0 and UART1	P15/ $\overline{\text{SCK1}}$
ASCK1				P25/ $\overline{\text{SCK3}}$
ASTB	Output	No	External address strobe signal output	P94
AV _{DD}	–	–	Positive power supply for A/D converter and ports used for alternate functions	–
AV _{REF}	Input	–	Reference voltage input for A/D converter	–
AV _{SS}	–	–	Ground potential for A/D converter and ports used for alternate functions	–
BV _{DD}	–	–	Positive power supply for bus interface and ports used for alternate functions	–
BV _{SS}	–	–	Ground potential for bus interface and ports used for alternate functions	–
CLKOUT	Output	–	Internal system clock output	–
CLO	Output	No	CLO output signal	P123
CSYNCIN	Input	No	Csync signal input	P164
$\overline{\text{DSTB}}$	Output	No	External data strobe signal output	P93/ $\overline{\text{RD}}$
$\overline{\text{HLD}}\text{AK}$	Output	No	Bus hold acknowledge output	P95
$\overline{\text{HLD}}\text{RQ}$	Input	No	Bus hold request input	P96
HSOUT0	Output	No	Hsync signal output before compensation	P166
HSOUT1			Hsync signal output after compensation	P167
INTCP80 to INTCP83	Input	No	External capture input for CC80 to CC83	P130 to P133
INTCP90 to INTCP93	Input	No	External capture input for CP90 to CP93	P140 to P143
INTP0 to INTP3	Input	Yes	External interrupt request input (analog noise elimination)	P01 to P04
INTP4			External interrupt request input (digital noise elimination)	P05/ADTRG
INTP5				P06/RTPTRG0
INTP6			External interrupt request input (digital noise elimination supporting remote controller)	P07

Remark PULL: On-chip pull-up resistor

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Pin Name	I/O	PULL	Function	Alternate Function
INTTCLR8	Input	No	External interrupt request input (digital noise elimination)	P135/TCLR8
INTTI8	Input	No		P134/TI8
INTTI9				P144/TI9
KR0 to KR7	Input	Yes	Key return input	P170 to P177
LBEN	Output	No	Lower byte enable signal output for external data bus	P90/WRL
NMI	Input	Yes	Non-maskable interrupt request input	P00
PWM0 to PWM3	Output	No	Output of PWM channels 0 to 3	P160 to P163
RD	Output	No	Bus read strobe signal output	P93/DSTB
RESET	Input	–	System reset input	–
RTP00 to RTP07	Output	Yes	Real-time output port	P100 to P107
RTP10 to RTP17		No		P150 to P157
RTPTRG0	Input	Yes	RTP external trigger input	P06
RTPTRG1		No		P145
R/W	Output	No	External read/write status output	P92/WRH
RXD0	Input	Yes	Serial receive data input for UART0 and UART1	P13/SI1
RXD1				P23/SI3
SCK0	I/O	Yes	Serial clock I/O for CSI0 to CSI3 (3-wire mode)	P12/SCL0
SCK1				P15/ASCK0
SCK2				P22/SCL1
SCK3				P25/ASCK1
SCK4		No	Variable-length CSI4 serial clock I/O	P122
SCL0	I/O	Yes	Serial clock I/O for I ² C0 and I ² C1 (μPD70F3038Y, 70F3040Y)	P12/SCK0
SCL1				P22/SCK2
SDA0	I/O	Yes	Serial transmit/receive data I/O for I ² C0 and I ² C1 (μPD70F3038Y, 70F3040Y)	P10/SI0
SDA1				P20/SI2
SI0	Input	Yes	Serial receive data input for CSI0 to CSI3 (3-wire mode)	P10/SDA0
SI1				P13/RXD0
SI2				P20/SDA1
SI3				P23/RXD1
SI4		No	Variable-length CSI4 serial receive data input	P120
SO0	Output	Yes	Serial transmit data output for CSI0 to CSI3	P11
SO1				P14/TXD0
SO2				P21
SO3				P24/TXD1
SO4		No	Variable-length CSI4 serial transmit data output	P121
TCLR8	Input	No	External clear input for TM8	P135/INTTCLR8

Remark PULL: On-chip pull-up resistor

Pin Name	I/O	PULL	Function	Alternate Function
TI000	Input	Yes	External count clock input/external capture trigger input for TM0	P30
TI001			External capture trigger input for TM0	P31
TI010			External count clock input/external capture trigger input for TM1	P32
TI011			External capture trigger input for TM1	P33
TI2			External count clock input for TM2	P26/TO2
TI3			External count clock input for TM3	P27/TO3
TI4			External count clock input for TM4	P36/TO4
TI5			External count clock input for TM5	P37/TO5
TI6		No	External count clock input for TM6	P124/TO6
TI7			External count clock input for TM7	P125/TO7
TI8			External count clock input for TM8	P134/INTTI8
TI9	External count clock input for TM9		P144/INTTI9	
TI10	External count clock input for TM10		P126/TO10	
TI11	External count clock input for TM11	P127/TO11		
TO0	Output	Yes	Pulse signal output for TM0	P34
TO1			Pulse signal output for TM1	P35
TO2			Pulse signal output for TM2	P26/TI2
TO3			Pulse signal output for TM3	P27/TI3
TO4			Pulse signal output for TM4	P36/TI4
TO5		Pulse signal output for TM5	P37/TI5	
TO6		No	Pulse signal output for TM6	P124/TI6
TO7			Pulse signal output for TM7	P125/TI7
TO80			Pulse signal output 0 for TM8	P136
TO81			Pulse signal output 1 for TM8	P137
TO10			Pulse signal output for TM10	P126/TI10
TO11	Pulse signal output for TM11		P127/TI11	
TXD0	Output	Yes	Serial transmit data output for UART0 and UART1	P14/SO1
TXD1				P24/SO3
UBEN	Output	No	Higher byte enable signal output for external data bus	P91
V _{DD}	-	-	Positive power supply pin	-
V _{PP}	-	-	High voltage application pin for program write/verify	-
VSOUT	Output	No	Vsync signal output	P165
V _{SS}	-	-	Ground potential	-
WAIT	Input	-	External WAIT signal input	-
WRH	Output	No	Higher byte write strobe signal output for external data bus	P92/R \overline{W}
WRL				P90/LBEN

Remark PULL: On-chip pull-up resistor

(4/4)

Pin Name	I/O	PULL	Function	Alternate Function
X1	Input	-	Resonator connection for main system clock	-
X2	-			-
XT1	Input	-	Resonator connection for subsystem clock	-
XT2	-			-

Remark PULL: On-chip pull-up resistor

1.3 Pin I/O Circuits, I/O Buffer Supply, and Recommended Connection of Unused Pins

Table 1-1 shows the I/O circuit type of each pin and the recommended connection of unused pins.

For the I/O configuration of each circuit type, refer to Figure 1-1.

Table 1-1. Types of Pin I/O Circuits and Recommended Connection of Unused Pins (1/2)

Pin	Alternate Function	I/O Circuit Type	I/O Buffer Power Supply	Recommended Connection Method	
P00	NMI	5-W	V _{DD}	Input: Independently connect to V _{DD} or V _{SS} via a resistor Output: Leave open	
P01 to P04	INTP0 to INTP3				
P05	INTP4/ADTRG				
P06	INTP5/RTPTRG0				
P07	INTP6				
P10	SI0/SDA0	10-F	V _{DD}		
P11	SO0	10-E			
P12	SCK0/SCL0	10-F			
P13	SI1/RXD0	5-W			
P14	SO1/TXD0	10-E			
P15	SCK1/ASCK0	10-F			
P20	SI2/SDA1	10-F	V _{DD}		
P21	SO2	10-E			
P22	SCK2/SCL1	10-F			
P23	SI3/RXD1	5-W			
P24	SO3/TXD1	10-E			
P25	SCK3/ASCK1	10-F			
P26, P27	TI2/TO2, TI3/TO3	5-W	V _{DD}		
P30, P31	TI000, TI001	5-W			
P32, P33	TI010, TI011	5-A			
P34, P35	TO0, TO1				
P36	TI4/TO4	5-W			
P37	TI5/TO5	5			
P40 to P47	AD0 to AD7				
P50 to P57	AD8 to AD15				
P60 to P65	A16 to A21				
P70 to P77	ANI0 to ANI7	9	AV _{DD}		Connect to AV _{SS}
P80 to P87	ANI8 to ANI15	9	AV _{DD}		
P90	LBEN/WRL	5	BV _{DD}		Input: Independently connect to BV _{DD} or BV _{SS} via a resistor Output: Leave open
P91	UBEN				
P92	R/W/WRH				
P93	DSTB/RD				
P94	ASTB				
P95	HLDK				
P96	HLDK				
P100 to P107	RTP00 to RTP07	10-E	V _{DD}	Input: Independently connect to V _{DD} or V _{SS} via a resistor Output: Leave open	
P110 to P113	–	5	V _{DD}		
P120	SI4	5-K	V _{DD}		

Table 1-1. Types of Pin I/O Circuits and Recommended Connection of Unused Pins (2/2)

Pin	Alternate Function	I/O Circuit Type	I/O Buffer Power Supply	Recommended Connection Method
P121	SO4	10-G	V _{DD}	Input: Independently connect to V _{DD} or V _{SS} via a resistor Output: Leave open
P122	SCK4	10-H		
P123	CLO	5		
P124	TI6/TO6	5-K		
P125	TI7/TO7			
P126	TI10/TO10			
P127	TI11/TO11			
P130 to P133	INTCP80 to INTCP83	5-K	V _{DD}	
P134	TI8/INTTI8			
P135	TCLR8/INTTCLR8			
P136, P137	TO80, TO81	5	V _{DD}	
P140 to P143	INTCP90 to INTCP93	5-K		
P144	TI9/INTTI9			
P145	RTPTRG1			
P146, P147	–	5	V _{DD}	
P150 to P157	RTP10 to RTP17	5		
P160 to P163	PWM0 to PWM3	5	V _{DD}	
P164	CSYNCIN	5-K		
P165	VSOUT	5		
P166	HSOUT0			
P167	HSOUT1			
P170 to P177	KR0 to KR7	5-K	V _{DD}	Leave open
P180 to P187	–	5	V _{DD}	
P190 to P197	–	5	V _{DD}	
CLKOUT	–	4	BV _{DD}	Leave open
WAIT	–	1	BV _{DD}	Connect to V _{DD} via a resistor
RESET	–	2	V _{DD}	–
X1	–	–	V _{DD}	–
X2	–	–	V _{DD}	Leave open
XT1	–	16-A	V _{DD}	Connect to V _{SS}
XT2	–	16-A	V _{DD}	Leave open
AV _{REF}	–	–	–	Connect to AV _{SS}
V _{PP}	–	–	–	Connect to V _{SS}
V _{DD}	–	–	–	–
V _{SS}	–	–	–	–
AV _{DD}	–	–	–	Connect to V _{DD}
AV _{SS}	–	–	–	Connect to V _{SS}
BV _{DD}	–	–	–	Connect to V _{DD}
BV _{SS}	–	–	–	Connect to V _{SS}

Figure 1-1. Pin I/O Circuits (1/2)

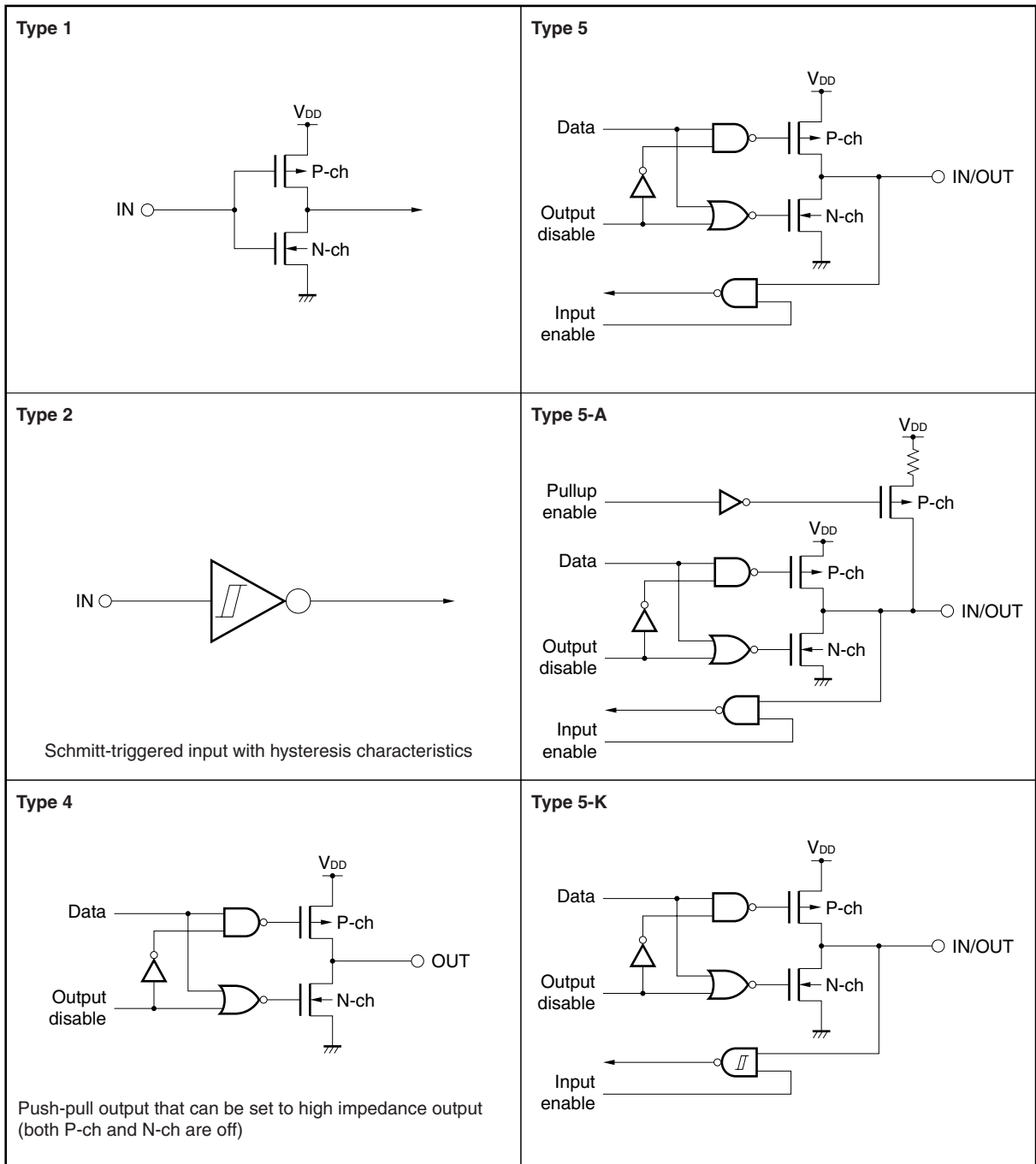
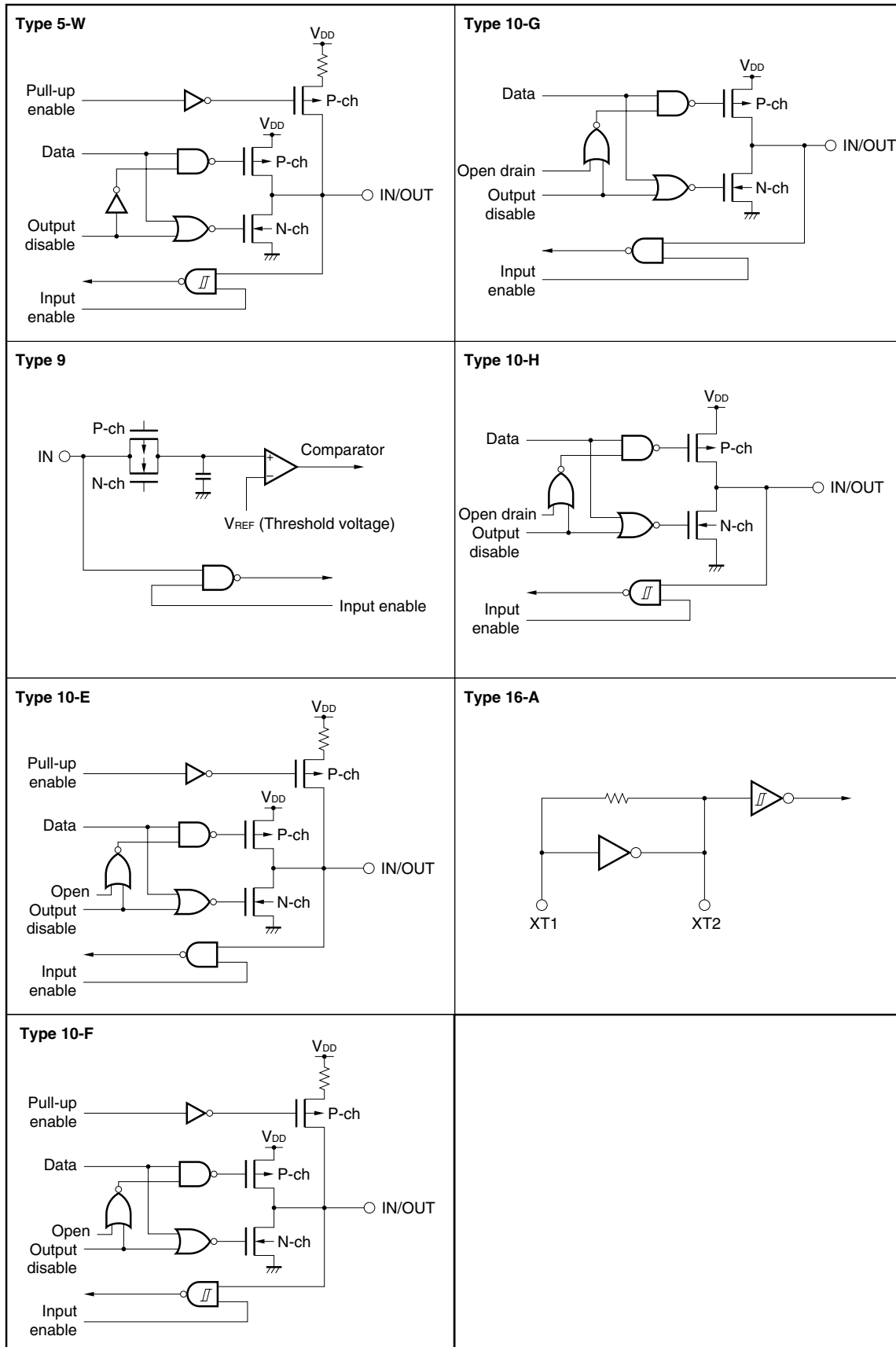


Figure 1-1. Pin I/O Circuits (2/2)



2. ELECTRICAL SPECIFICATIONS

Absolute Maximum Ratings (T_A = 25°C, V_{SS} = 0 V)

Parameter	Symbol	Conditions	Ratings	Unit
Supply voltage	V _{DD}		-0.5 to +4.6	V
	V _{PP}		-1.5 to +8.5	V
	AV _{DD}		-0.5 to +4.6	V
	BV _{DD}		-0.5 to +4.6	V
	V _{SS}		-0.5 to +0.5	V
	AV _{SS}		-0.5 to +0.5	V
	BV _{SS}		-0.5 to +0.5	V
Input voltage	V _{I1}	Note 1 (V _{DD})	-0.5 to V _{DD} + 0.5 ^{Note 4}	V
	V _{I2}	Note 2 (BV _{DD})	-0.5 to BV _{DD} + 0.5 ^{Note 4}	V
Clock input voltage	V _K	X1, V _{DD} = 2.7 to 3.6 V	-0.5 to V _{DD} + 1.0 ^{Note 4}	V
Analog input voltage	V _{IAN}	Note 3 (AV _{DD})	-0.5 to AV _{DD} + 0.5 ^{Note 4}	V
Analog reference input voltage	AV _{REF}	AV _{REF} pin	-0.5 to AV _{DD} + 0.5 ^{Note 4}	V
Output current, low	I _{OL}	Per pin	4.0	mA
		Total for P00 to P07 and P150 to P157	25	mA
		Total for P100 to P107 and P160 to P167	25	mA
		Total for P170 to P177 and P190 to P197	25	mA
		Total for P124 to P127 and P180 to P187	25	mA
		Total for P30 to P37 and P120 to P123	25	mA
		Total for P12 to P15, P20 to 27, and P110 to P113	25	mA
		Total for P50 to P57, P60 to P65, and CLKOUT	25	mA
		Total for P40 to P47 and P90 to P96	25	mA
		Total for P130 to P137 and P140 to P147	25	mA
Output current, high	I _{OH}	Per pin	-4.0	mA
		Total for P00 to P07 and P150 to P157	-25	mA
		Total for P100 to P107 and P160 to P167	-25	mA
		Total for P170 to P177 and P190 to P197	-25	mA
		Total for P124 to P127 and P180 to P187	-25	mA
		Total for P30 to P37 and P120 to P123	-25	mA
		Total for P12 to P15, P20 to 27, and P110 to P113	-25	mA
		Total for P50 to P57, P60 to P65, and CLKOUT	-25	mA
		Total for P40 to P47 and P90 to P96	-25	mA
		Total for P130 to P137 and P140 to P147	-25	mA
Output voltage	V _{O1}	Note 1 , V _{DD} = 2.7 to 3.6V	-0.5 to V _{DD} + 0.5 ^{Note 4}	V
	V _{O2}	Note 2 , CLKOUT, BV _{DD} = 2.7 to 3.6V	-0.5 to BV _{DD} + 0.5 ^{Note 4}	V
Operating ambient temperature	T _A	Normal operation mode	-40 to +85	°C
		Flash programming mode	+10 to +40	°C
Storage temperature	T _{stg}		-40 to +125	°C

- Notes 1.** Ports 0, 1, 2, 3, 10, 11, 12, 13, 14, 15, 16, 17, 18, and 19 (includes alternate function pins)
- 2.** Ports 4, 5, 6, and 9 (includes alternate function pins)
- 3.** Ports 7 and 8 (includes alternate function pins)
- 4.** Be sure not to exceed each absolute maximum rating (MAX.).

- Cautions**
1. Avoid direct connections among the IC device output (or I/O) pins and between V_{DD} or V_{CC} and GND. However, direct connections among open-drain and open-collector pins are possible, as are direct connections to external circuits that have timing designed to prevent output contention with pins that become high-impedance.
 2. Product quality may suffer if the absolute maximum rating is exceeded even momentarily for any parameter. That is, the absolute maximum ratings are rated values at which the product is on the verge of suffering physical damage, and therefore the product must be used under conditions that ensure that the absolute maximum ratings are not exceeded.
- The ratings and conditions indicated for DC characteristics and AC characteristics represent the quality assurance range during normal operation.

Capacitance ($T_A = 25^\circ\text{C}$, $V_{DD} = AV_{DD} = BV_{DD} = V_{SS} = 0\text{ V} = AV_{SS} = BV_{SS}$)

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Input capacitance	C_i	$f_c = 1\text{ MHz}$ Unmeasured pins returned to 0 V			15	pF
I/O capacitance	C_{IO}				15	pF
Output capacitance	C_o				15	pF

★ **Operating Conditions**

(1) CPU operating frequency

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
CPU operating frequency	f_{CPU}	$V_{DD} = 2.7\text{ to }3.6\text{ V}$	0.5		16	MHz
		$V_{DD} = 3.1\text{ to }3.6\text{ V}$	0.5		20	MHz

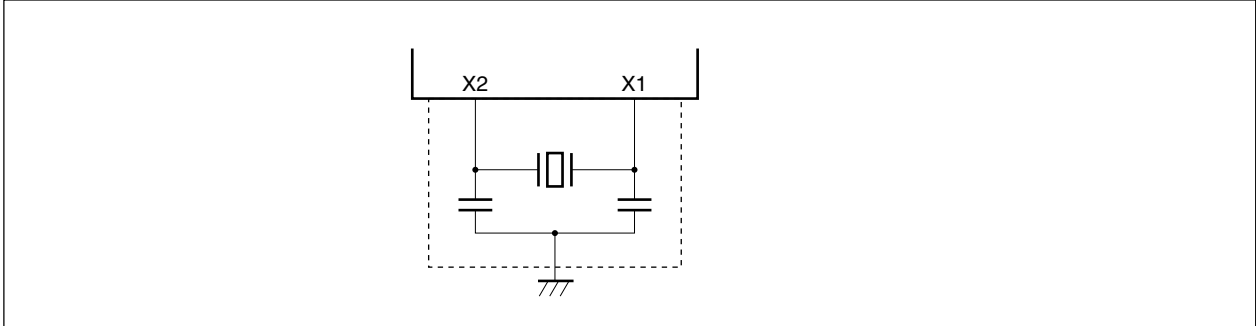
(2) Operating frequency for each supply voltage

Operating Frequency	Supply Voltage ($V_{DD} = AV_{DD} = BV_{DD}$)
$4\text{ MHz} \leq f_{xx} \leq 16\text{ MHz}$	2.7 to 3.6 V
$4\text{ MHz} \leq f_{xx} \leq 20\text{ MHz}$	3.1 to 3.6 V
$f_{XT} = 32.768\text{ kHz}$ (only watch operation)	2.7 to 3.6 V

Recommended Oscillator

(1) Main clock oscillator (T_A = -40 to +85°C)

(a) Ceramic or crystal resonator connection



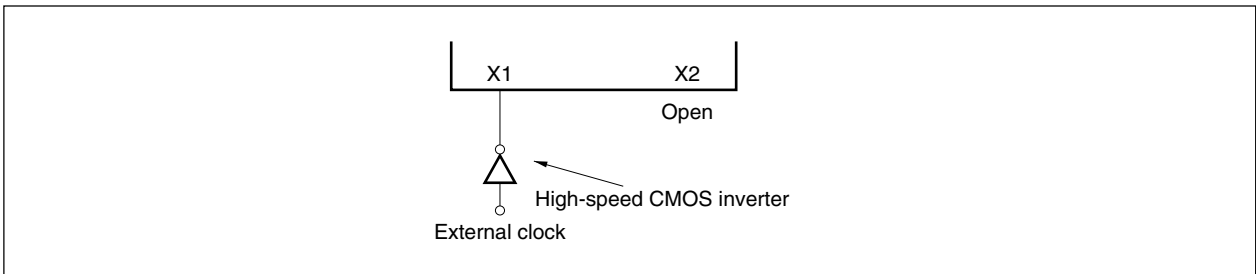
Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Oscillation frequency	f _{xx}	V _{DD} = 2.7 to 3.6 V	4		16	MHz
		V _{DD} = 3.1 to 3.6 V	4		20	MHz
Oscillation stabilization time		After reset release		2 ¹⁹ /f _{xx}		s
		After STOP mode release		Note		s

★

Note Values vary depending on the settings of the oscillation stabilization selection register (OSTS).

- Remarks**
1. Place the oscillator as close as possible to X1 and X2.
 2. Do not wire other signal lines within the broken lines.
 3. For resonator selection and oscillation constants, customers are advised to either evaluate the oscillation themselves, or apply to the resonator manufacturer for evaluation.

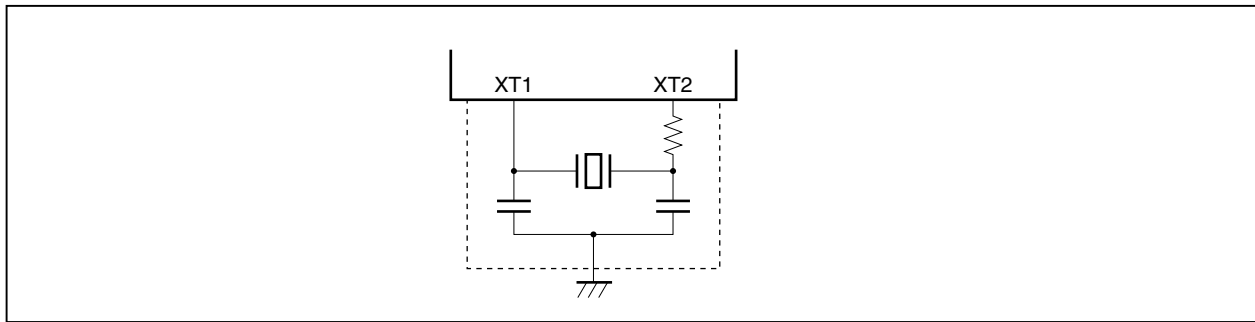
(b) External clock input



Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Input frequency	f _{xx}	V _{DD} = 2.7 to 3.6 V	4		16	MHz
		V _{DD} = 3.1 to 3.6 V	4		20	MHz

- Cautions**
1. Place the high-speed CMOS inverter as close as possible to the X1 pin.
 2. Perform sufficient evaluation to determine whether the μPD70F3038, 70F3038Y, 70F3040, or 70F3040Y matches the high-speed inverter.

(2) Subclock oscillator ($T_A = -40$ to $+85^\circ\text{C}$)



Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Oscillation frequency	f_{XT}	$V_{DD} = 2.7$ to 3.6 V	32	32.768	35	kHz
Oscillation stabilization time				10		s

- Remarks**
1. Place the oscillator as close as possible to XT1 and XT2.
 2. Do not wire other signal lines within the broken lines.
 3. For resonator selection and oscillation constants, customers are advised to either evaluate the oscillation themselves, or apply to the resonator manufacturer for evaluation.

★ DC Characteristics

(1) 16 MHz operation (T_A = -40 to +85°C, V_{DD} = AV_{DD} = BV_{DD} = 2.7 to 3.6 V, V_{SS} = AV_{SS} = BV_{SS} = 0 V)

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Input voltage, high	V _{IH1}	Pins in Note 1 , WAIT	0.7BV _{DD}		BV _{DD}	V
	V _{IH2}	Pins in Note 2	0.7V _{DD}		V _{DD}	V
	V _{IH3}	Pins in Note 3 , RESET	0.75V _{DD}		V _{DD}	V
	V _{IH4}	Pins in Note 4	0.7AV _{DD}		AV _{DD}	V
	V _{IH5}	X1	0.8V _{DD}		V _{DD}	V
Input voltage, low	V _{IL1}	Pins in Note 1 , WAIT	BV _{SS}		0.3BV _{DD}	V
	V _{IL2}	Pins in Note 2	V _{SS}		0.3V _{DD}	V
	V _{IL3}	Pins in Note 3 , RESET	V _{SS}		0.2V _{DD}	V
	V _{IL4}	Pins in Note 4	AV _{SS}		0.3AV _{DD}	V
	V _{IL5}	X1	V _{SS}		0.2V _{DD}	V
V _{PP} supply current	V _{PP1}	During normal operation	0		0.2V _{DD}	V
Output voltage, high	V _{OH1}	Note 1 , CLKOUT	I _{OH} = -3 mA	0.8BV _{DD}		V
	V _{OH2}	Notes 2, 3	I _{OH} = -1 mA	0.8V _{DD}		V
Output voltage, low	V _{OL1}	Note 1 , CLKOUT			0.4	V
	V _{OL2}	Notes 2, 3 (excluding P10, P12, P20, P22)			0.4	V
	V _{OL3}	P10, P12, P20, P22			0.4	V
Input leakage current, high	I _{LIH1}	V _I = V _{DD} = AV _{DD} = BV _{DD}	Other than X1		5	μA
	I _{LIH2}		X1		20	μA
Input leakage current, low	I _{LIL1}	V _I = 0 V	Other than X1		-5	μA
	I _{LIL2}		X1		-20	μA
Output leakage current, high	I _{LOH}	V _O = V _{DD} = AV _{DD} = BV _{DD}			5	μA
Output leakage current, low	I _{LOL}	V _O = 0 V			-5	μA
Supply current	I _{DD1}	Normal operation (f _{xx} = 16 MHz)		40	58	mA
	I _{DD2}	HALT mode (f _{xx} = 16 MHz)		19	32	mA
	I _{DD3}	IDLE mode (f _{xx} = 16 MHz)		6	9	mA
	I _{DD4}	STOP mode (subclock operation: f _{XT} = 32.768 kHz, watch timer operation)		13	115	μA
		STOP mode (subclock stopped, XT1 = V _{SS})		5	100	μA
Pull-up resistor	R _L	V _{IN} = 0V	10	30	100	kΩ

Notes 1. Ports 4, 5, 6, and 9 (includes alternate function pins)

2. P11, P14, P21, P24, P34, P35, P100 to P107, P110 to P113, P121, P123, P136, P137, P146, P147, P150 to P157, P160 to P163, P165 to P167, P180 to P187, and P190 to P197 (includes alternate function pins)

3. P00 to P07, P10, P12, P13, P15, P20, P22, P23, P25 to P27, P30 to P33, P36, P37, P120, P122, P124 to P127, P130 to P135, P140 to P145, P164, and P170 to P177 (includes alternate function pins)

4. Ports 7, and 8 (includes alternate function pins)

Caution The TYP. value of V_{DD} is 3.3 V. The current that is consumed at output buffers is not included.

(2) 20 MHz operation

($T_A = -40$ to $+85^\circ\text{C}$, $V_{DD} = AV_{DD} = BV_{DD} = 3.1$ to 3.6 V, $V_{SS} = AV_{SS} = BV_{SS} = 0$ V)

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Input voltage, high	V_{IH1}	Pins in Note 1 , $\overline{\text{WAIT}}$	$0.7 BV_{DD}$		BV_{DD}	V
	V_{IH2}	Pins in Note 2	$0.7 V_{DD}$		V_{DD}	V
	V_{IH3}	Pins in Note 3 , $\overline{\text{RESET}}$	$0.75 V_{DD}$		V_{DD}	V
	V_{IH4}	Pins in Note 4	$0.7 AV_{DD}$		AV_{DD}	V
	V_{IH5}	X1	$0.8 V_{DD}$		V_{DD}	V
Input voltage, low	V_{IL1}	Pins in Note 1 , $\overline{\text{WAIT}}$	BV_{SS}		$0.3 BV_{DD}$	V
	V_{IL2}	Pins in Note 2	V_{SS}		$0.3 V_{DD}$	V
	V_{IL3}	Pins in Note 3 , $\overline{\text{RESET}}$	V_{SS}		$0.2 V_{DD}$	V
	V_{IL4}	Pins in Note 4	AV_{SS}		$0.3 AV_{DD}$	V
	V_{IL5}	X1	V_{SS}		$0.2 V_{DD}$	V
V_{PP} supply voltage	V_{PP1}	Normal operation	0		$0.2 V_{DD}$	V
Output voltage, high	V_{OH1}	Note 1 , CLKOUT	$I_{OH} = -3$ mA	$0.8 BV_{DD}$		V
	V_{OH2}	Notes 2, 3	$I_{OH} = -1$ mA	$0.8 V_{DD}$		V
Output voltage, low	V_{OL1}	Note 1 , CLKOUT	$I_{OL} = 1.6$ mA		0.4	V
	V_{OL2}	Notes 2, 3 (excluding P10, P12, P20, P22)	$I_{OL} = 1.6$ mA		0.4	V
	V_{OL3}	P10, P12, P20, P22	$I_{OL} = 3$ mA		0.4	V
Input leakage current, high	I_{LIH1}	$V_i = V_{DD} = AV_{DD} = BV_{DD}$	Other than X1		5	μA
	I_{LIH2}	BV_{DD}	X1		20	μA
Input leakage current, low	I_{LIL1}	$V_i = 0$ V	Other than X1		-5	μA
	I_{LIL2}		X1		-20	μA
Output leakage current, high	I_{LOH}	$V_o = V_{DD} = AV_{DD} = BV_{DD}$			5	μA
Output leakage current,	I_{LOL}	$V_o = 0$ V			-5	μA
Supply current	I_{DD1}	Normal operation ($f_{xx} = 20$ MHz)		45	64	mA
	I_{DD2}	HALT mode ($f_{xx} = 20$ MHz)		20	35	mA
	I_{DD3}	IDLE mode ($f_{xx} = 20$ MHz)		6.5	10	mA
	I_{DD4}	STOP mode (subclock operation: $f_{XT} = 32.768$ kHz, watch timer operation)		13	115	μA
		STOP mode (subclock stopped, $XT1 = V_{SS}$)		5	100	μA
Pull-up resistor	R_L	$V_{IN} = 0$ V	10	30	100	$\text{k}\Omega$

- Notes 1.** Ports 4, 5, 6, and 9 (includes alternate function pins)
- 2.** P11, P14, P21, P24, P34, P35, P100 to P107, P110 to P113, P121, P123, P136, P137, P146, P147, P150 to P157, P160 to P163, P165 to P167, P180 to P187, and P190 to P197 (includes alternate function pins)
- 3.** P00 to P07, P10, P12, P13, P15, P20, P22, P23, P25 to P27, P30 to P33, P36, P37, P120, P122, P124 to P127, P130 to P135, P140 to P145, P164, and P170 to P177 (includes alternate function pins)
- 5.** Ports 7 and 8 (includes alternate function pins)

Caution The TYP. value of V_{DD} is 3.3 V. The current that is consumed at output buffers is not included.

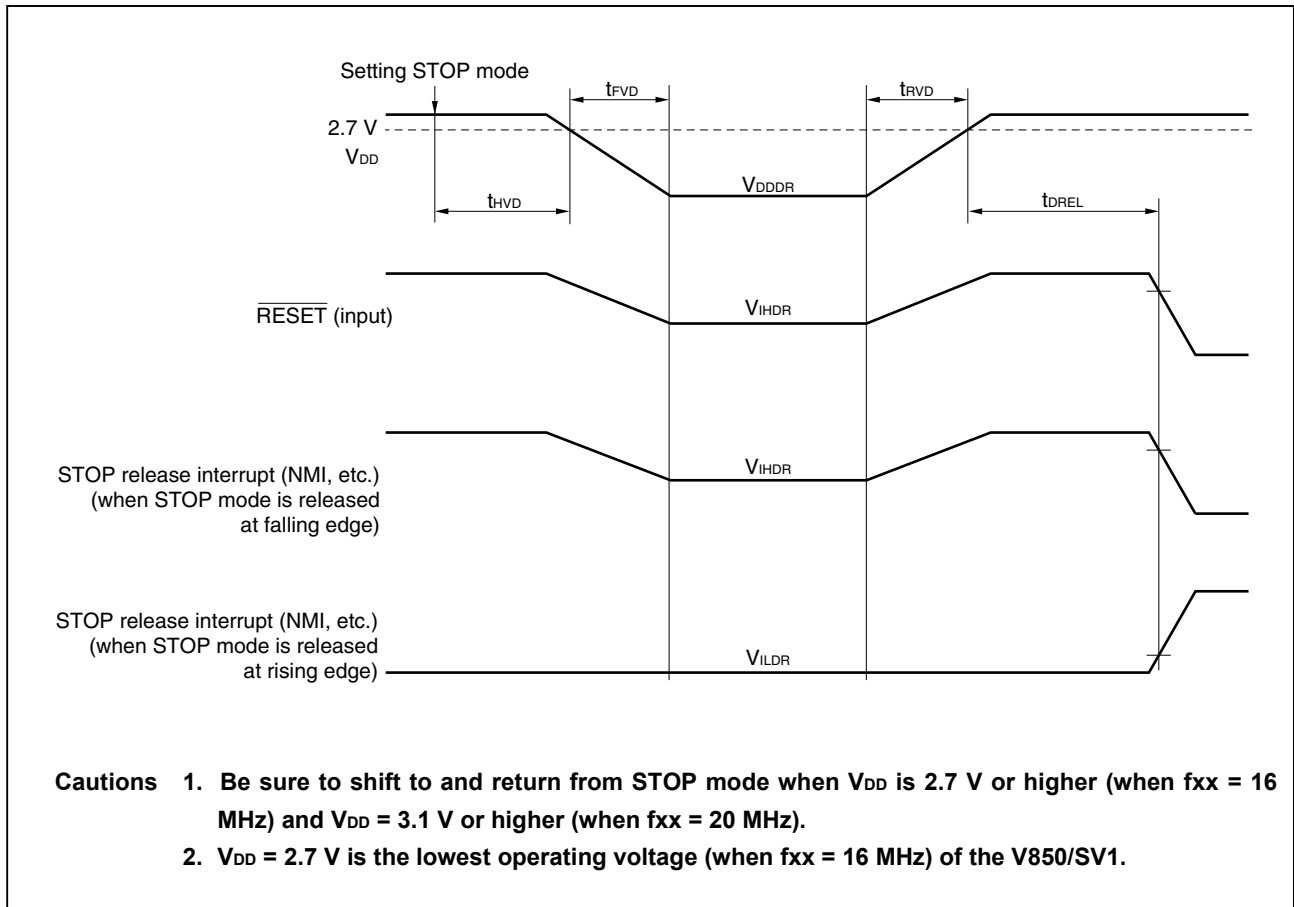
Data Retention Characteristics

($T_A = -40$ to $+85^\circ\text{C}$, $V_{SS} = AV_{SS} = BV_{SS} = 0$ V, $C_L = 50$ pF)

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Data retention voltage	V_{DDDR}	STOP mode	1.8		3.6	V
Data retention current	I_{DDDR}	V_{DDDR} [V], $XT1 = V_{SS}$		5	100	μA
Supply voltage rise time	t_{rVD}		200			μs
Supply voltage fall time	t_{fVD}		200			μs
Supply voltage hold time (from STOP mode setting)	t_{HVD}		0			ms
STOP release signal input time	t_{dREL}		0			ms
Data retention high-level input voltage	V_{IHDR}	All input ports	V_{IHn}		V_{DDDR}	V
Data retention low-level input voltage	V_{ILDR}	All input ports	0		V_{ILn}	V

Remark n = 1 to 5

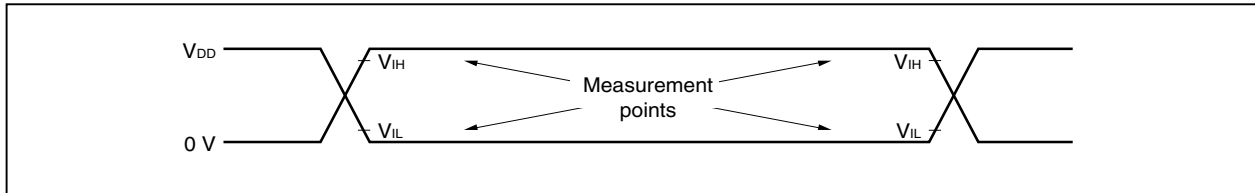
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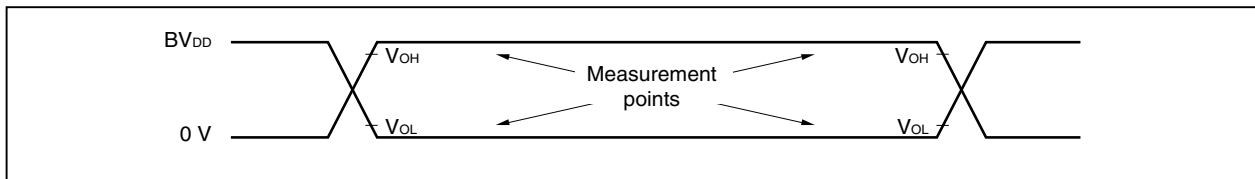
- Cautions**
1. Be sure to shift to and return from STOP mode when V_{DD} is 2.7 V or higher (when $f_{xx} = 16$ MHz) and $V_{DD} = 3.1$ V or higher (when $f_{xx} = 20$ MHz).
 2. $V_{DD} = 2.7$ V is the lowest operating voltage (when $f_{xx} = 16$ MHz) of the V850/SV1.

AC Characteristics

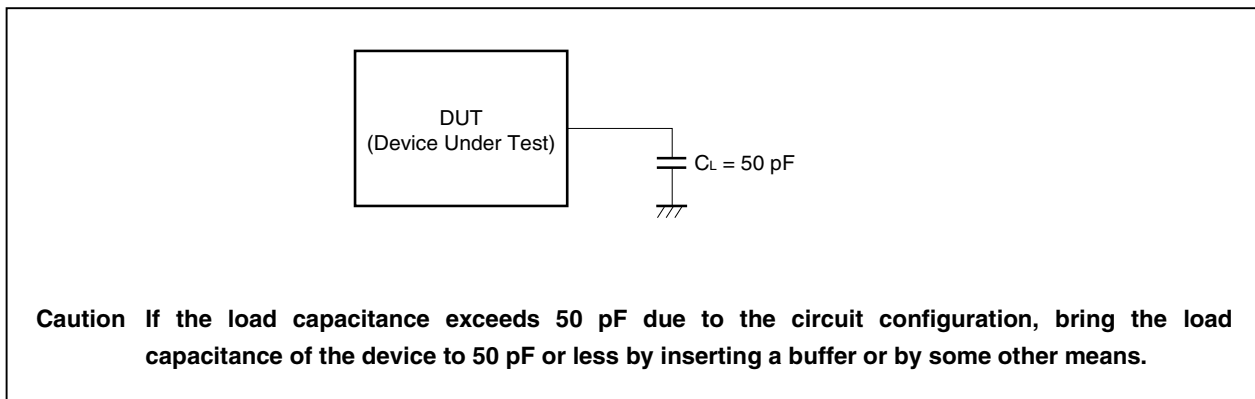
AC Test Input Measurement points (V_{DD} , BV_{DD} , AV_{DD})



AC Test Output Measurement points (BV_{DD} , V_{DD})



Load Conditions



Clock Timing

(1) 16 MHz operation

($T_A = -40$ to $+85^\circ\text{C}$, $V_{DD} = AV_{DD} = BV_{DD} = 2.7$ to 3.6 V, $V_{SS} = AV_{SS} = BV_{SS} = 0$ V, $C_L = 50$ pF)

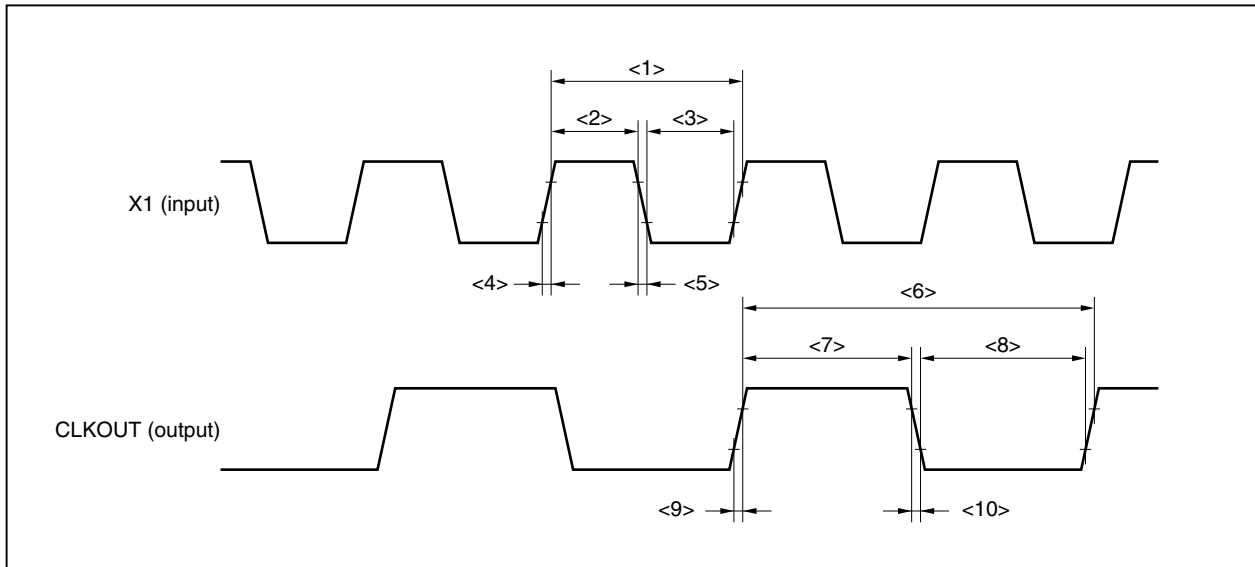
Parameter	Symbol		Conditions	MIN.	MAX.	Unit
X1 input cycle	t_{CYX}	<1>		62.5	250	ns
X1 input high-level width	t_{WXH}	<2>		28.2		ns
X1 input low-level width	t_{WXL}	<3>		28.2		ns
X1 input rise time	t_{XR}	<4>			0.5 (<1>-<2>-<3>)	ns
X1 input fall time	t_{XF}	<5>			0.5 (<1>-<2>-<3>)	ns
CLKOUT output cycle	t_{CYK}	<6>		62.5 ns	2 μ s	
CLKOUT high-level width	t_{WKH}	<7>		$0.4t_{CYK}-10$		ns
CLKOUT low-level width	t_{WKL}	<8>		$0.4t_{CYK}-10$		ns
CLKOUT rise time	t_{KR}	<9>			10	ns
CLKOUT fall time	t_{KF}	<10>			10	ns

(2) 20 MHz operation

($T_A = -40$ to $+85^\circ\text{C}$, $V_{DD} = AV_{DD} = BV_{DD} = 3.1$ to 3.6 V, $V_{SS} = AV_{SS} = BV_{SS} = 0$ V, $C_L = 50$ pF)

Parameter	Symbol		Conditions	MIN.	MAX.	Unit
X1 input cycle	t_{CYX}	<1>		50.0	250	ns
X1 input high-level width	t_{WXH}	<2>		22.5		ns
X1 input low-level width	t_{WXL}	<3>		22.5		ns
X1 input rise time	t_{XR}	<4>			0.5 (<1>-<2>-<3>)	ns
X1 input fall time	t_{XF}	<5>			0.5 (<1>-<2>-<3>)	ns
CLKOUT output cycle	t_{CYK}	<6>		50 ns	2 μ s	
CLKOUT high-level width	t_{WKH}	<7>		$0.4t_{CYK}-10$		ns
CLKOUT low-level width	t_{WKL}	<8>		$0.4t_{CYK}-10$		ns
CLKOUT rise time	t_{KR}	<9>			10	ns
CLKOUT fall time	t_{KF}	<10>			10	ns

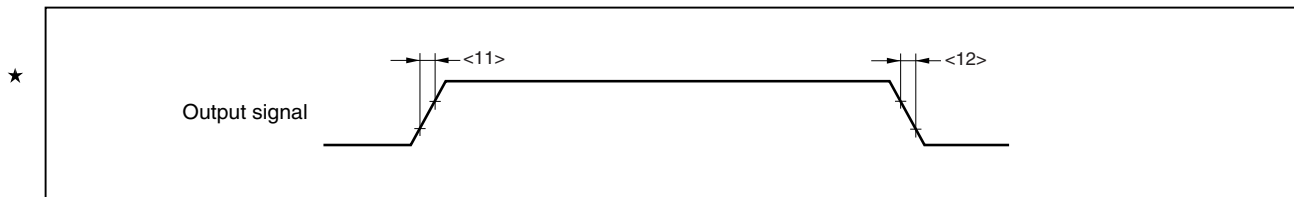
Clock Timing



Timing of Pins Other Than CLKOUT, P4, P5, P6, and P9 Pins

($T_A = -40$ to $+85^\circ\text{C}$, $V_{DD} = AV_{DD} = BV_{DD} = 2.7$ to 3.6 V, $V_{SS} = AV_{SS} = BV_{SS} = 0$ V, $C_L = 50$ pF)

Parameter	Symbol	Conditions	MIN.	MAX.	Unit
Output rise time	t_{oR}	<11>		20	ns
Output fall time	t_{oF}	<12>		20	ns



Bus Timing (CLKOUT Asynchronous)

($T_A = -40$ to $+85^\circ\text{C}$, $V_{DD} = AV_{DD} = BV_{DD} = 2.7$ to 3.6 V, $V_{SS} = AV_{SS} = BV_{SS} = 0$ V, $C_L = 50$ pF)

Parameter	Symbol	Conditions	MIN.	MAX.	Unit
Address setup time (to $ASTB\downarrow$)	t_{SAST} <13>		$0.5T - 20$		ns
Address hold time (from $ASTB\downarrow$)	t_{HSTA} <14>		$0.5T - 15$		ns
Delay time from $\overline{DSTB}\downarrow$ to address float	t_{FDA} <15>			2	ns
Setup time from address to data input	t_{SAID} <16>			$(2 + n)T - 30$	ns
Setup time from $\overline{DSTB}\downarrow$ to data input	t_{SDID} <17>			$(1 + n)T - 30$	ns
Delay time from $ASTB\downarrow$ to $\overline{DSTB}\downarrow$	t_{DSTD} <18>		$0.5T - 15$		ns
Data input hold time (from $\overline{DSTB}\uparrow$)	t_{HDID} <19>		0		ns
Address output time from $\overline{DSTB}\uparrow$	t_{DDA} <20>		$(1 + i)T - 15$		ns
Delay time from $\overline{DSTB}\uparrow$ to $ASTB\uparrow$	t_{DDST1} <21>		$0.5T - 15$		ns
Delay time from $\overline{DSTB}\uparrow$ to $ASTB\downarrow$	t_{DDST2} <22>		$(1.5 + i)T - 15$		ns
\overline{DSTB} low-level width	t_{WDL} <23>		$(1 + n)T - 15$		ns
$ASTB$ high-level width	t_{WSTH} <24>		$T - 15$		ns
Data output time from $\overline{DSTB}\downarrow$	t_{DDOD} <25>			15	ns
Data output setup time (to $\overline{DSTB}\uparrow$)	t_{SODD} <26>		$(1 + n)T - 20$		ns
Data output hold time (from $\overline{DSTB}\uparrow$)	t_{HDOD} <27>		$T - 15$		ns
\overline{WAIT} setup time (to address)	t_{SAWT1} <28>	$n \geq 1$		$1.5T - 30$	ns
	t_{SAWT2} <29>			$(1.5 + n)T - 30$	ns
\overline{WAIT} hold time (from address)	t_{HAWT1} <30>	$n \geq 1$	$(0.5 + n)T$		ns
	t_{HAWT2} <31>		$(1.5 + n)T$		ns
★ \overline{WAIT} setup time (to $ASTB\downarrow$)	t_{SSTWT1} <32>	$n \geq 1$		$T - 25$	ns
	t_{SSTWT2} <33>			$(1 + n)T - 25$	ns
★ \overline{WAIT} hold time (from $ASTB\downarrow$)	t_{HSTWT1} <34>	$n \geq 1$	$nT + 5$		ns
	t_{HSTWT2} <35>		$(1 + n)T + 5$		ns
\overline{HLDRQ} high-level width	t_{WHQH} <36>		$T + 10$		ns
\overline{HLDAK} low-level width	t_{WHAL} <37>		$T - 15$		ns
Delay time from $\overline{HLDAK}\uparrow$ to bus output	t_{DHAC} <38>		0		ns
★ Delay time from $\overline{HLDRQ}\downarrow$ to $\overline{HLDAK}\downarrow$	t_{DHQHA1} <39>			$(2n + 7.5)T + 25$	ns
★ Delay time from $\overline{HLDRQ}\uparrow$ to $\overline{HLDAK}\uparrow$	t_{DHQHA2} <40>		$0.5T$	$1.5T + 25$	ns

Remarks 1. $T = 1/f_{CPU}$ (f_{CPU} : CPU operation clock frequency)

2. n: Number of wait clocks inserted in the bus cycle.

Sampling timing changes when a programmable wait is inserted.

3. i: Number of idle states inserted after the read cycle (0 or 1).

4. The specifications described above are the values for when a clock with a duty ratio of 1:1 is input from X1.

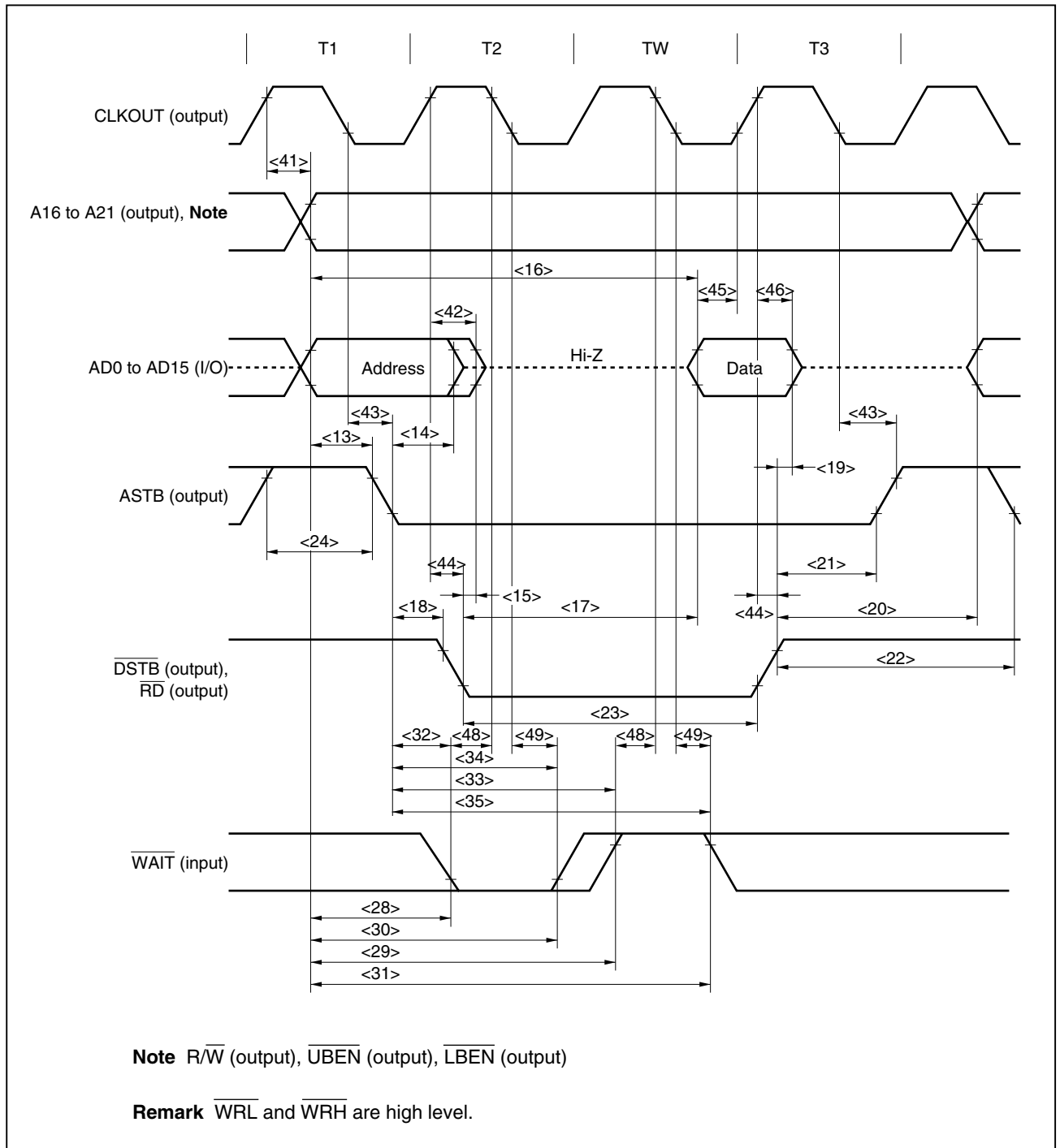
Bus Timing (CLKOUT Synchronous)

($T_A = -40$ to $+85^\circ\text{C}$, $V_{DD} = AV_{DD} = BV_{DD} = 2.7$ to 3.6 V, $V_{SS} = AV_{SS} = BV_{SS} = 0$ V, $C_L = 50$ pF)

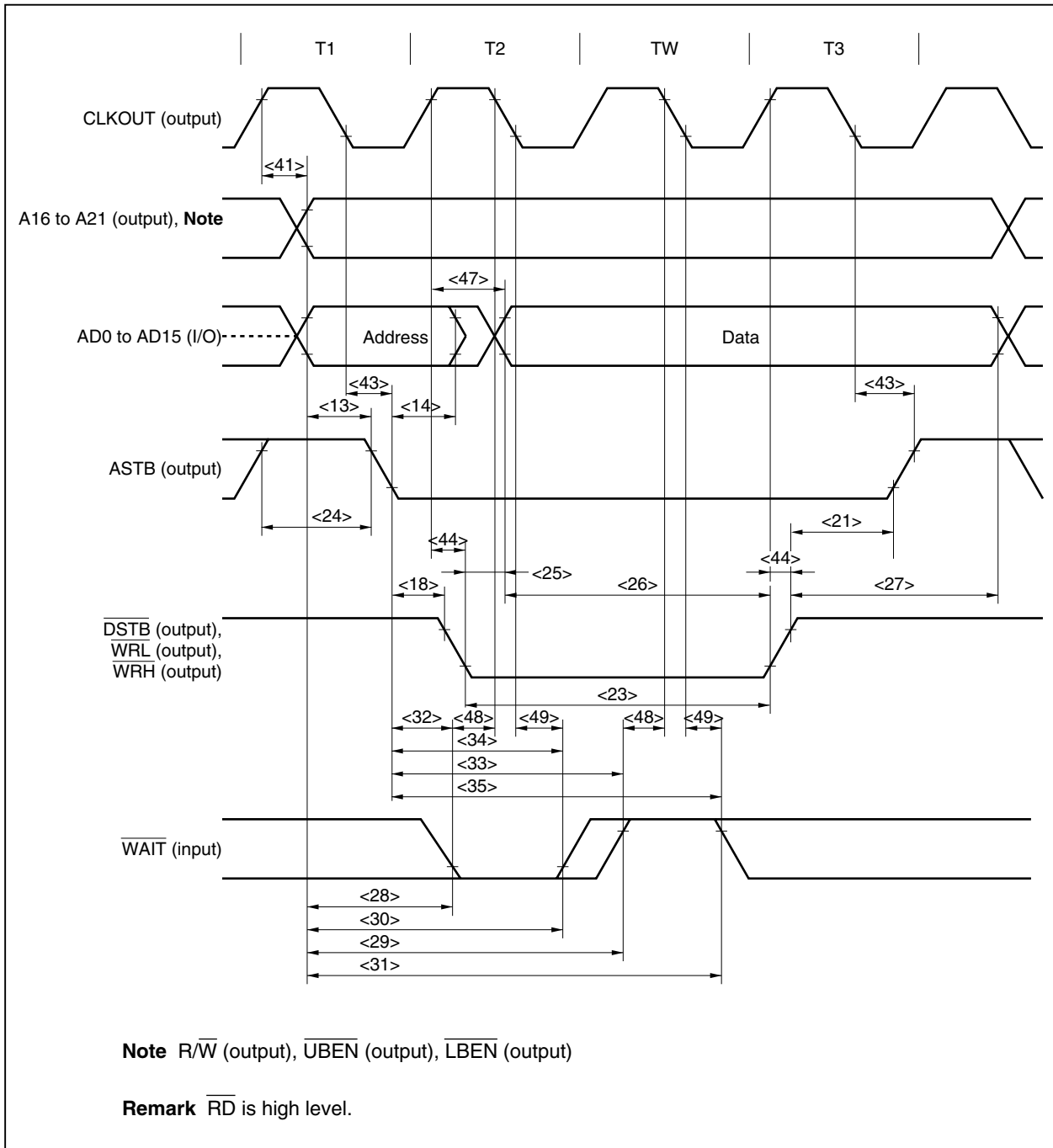
Parameter	Symbol	Conditions	MIN.	MAX.	Unit
Delay time from CLKOUT↑ to address	t_{DKA}	<41>	0	19	ns
Delay time from CLKOUT↑ to address float	t_{FKA}	<42>	-12	7	ns
Delay time from CLKOUT↓ to ASTB	t_{DKST}	<43>	-12	7	ns
Delay time from CLKOUT↑ to \overline{DSTB}	t_{DKD}	<44>	-5	14	ns
Data input setup time (to CLKOUT↑)	t_{SIDK}	<45>	15		ns
Data input hold time (from CLKOUT↑)	t_{HKID}	<46>	5		ns
Delay time from CLKOUT↑ to data output	t_{DKOD}	<47>		19	ns
\overline{WAIT} setup time (to CLKOUT↓)	t_{SWTK}	<48>	15		ns
\overline{WAIT} hold time (from CLKOUT↓)	t_{HKWT}	<49>	5		ns
\overline{HLDRQ} setup time (to CLKOUT↓)	t_{SHQK}	<50>	15		ns
\overline{HLDRQ} hold time (from CLKOUT↓)	t_{HKHQ}	<51>	5		ns
Delay time from CLKOUT↑ to bus float	t_{DKF}	<52>		19	ns
Delay time from CLKOUT↑ to \overline{HLDAK}	t_{DKHA}	<53>		19	ns

Remark The specifications described above are the values of when a clock with a duty ratio of 1:1 is input from X1.

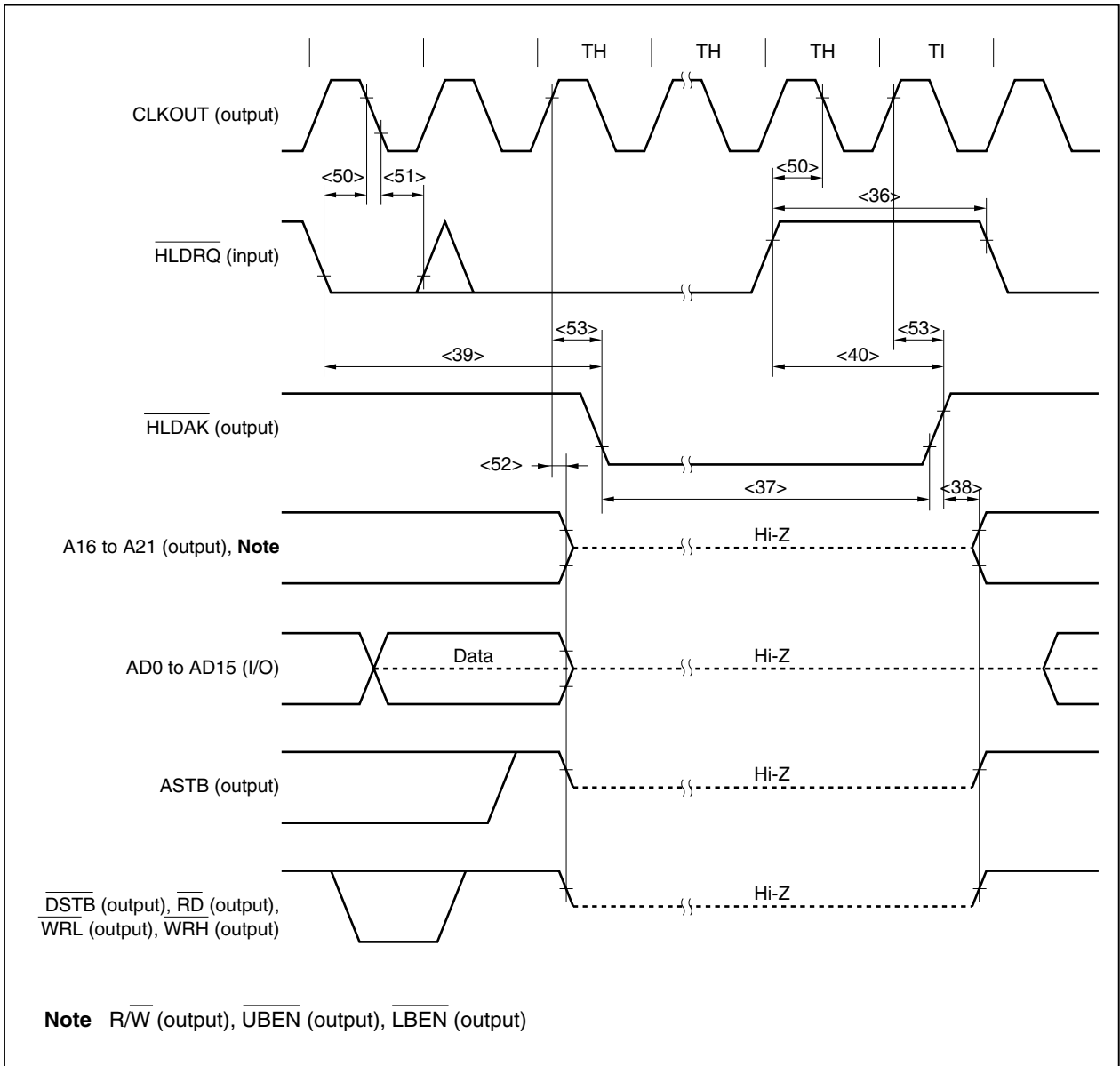
Read Cycle (CLKOUT Synchronous/Asynchronous, 1 Wait)



Write Cycle (CLKOUT Synchronous/Asynchronous, 1 Wait)



Bus Hold



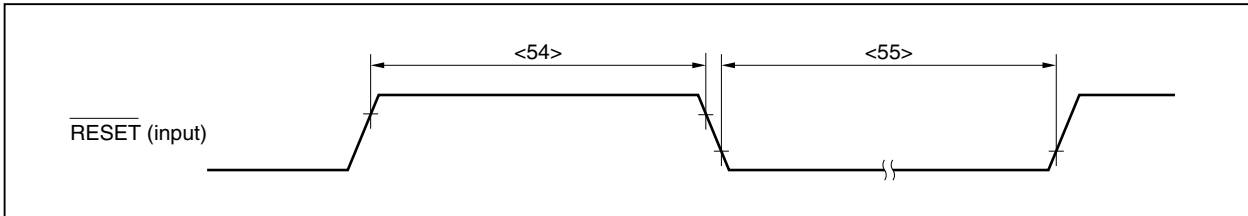
Reset/Interrupt Timing

($T_A = -40$ to $+85^\circ\text{C}$, $V_{DD} = AV_{DD} = BV_{DD} = 2.7$ to 3.6 V, $V_{SS} = AV_{SS} = BV_{SS} = 0$ V, $C_L = 50$ pF)

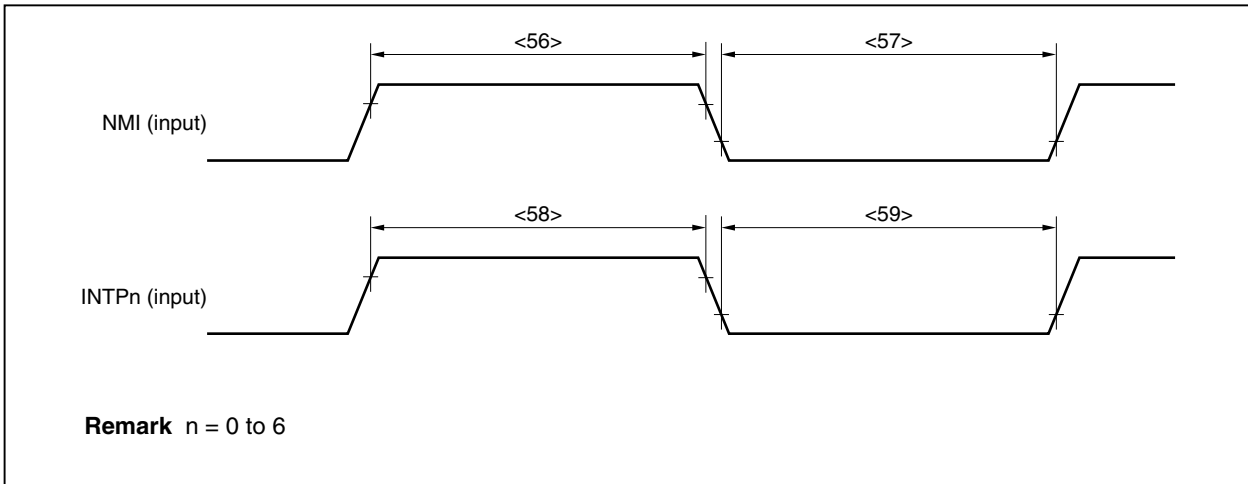
Parameter	Symbol	Conditions	MIN.	MAX.	Unit
RESET high-level width	t_{WRSH}	<54>	500		ns
RESET low-level width	t_{WRSL}	<55>	500		ns
NMI high-level width	t_{WNIH}	<56>	500		ns
NMI low-level width	t_{WNIL}	<57>	500		ns
INTPn high-level width	t_{WITH}	<58> n = 0 to 3, analog noise elimination	500		ns
		n = 4, 5, digital noise elimination	$3T + 20$		ns
		n = 6, digital noise elimination	$3T_{smp} + 20$		ns
INTPn low-level width	t_{WITL}	<59> n = 0 to 3, analog noise elimination	500		ns
		n = 4, 5, digital noise elimination	$3T + 20$		ns
		n = 6, digital noise elimination	$3T_{smp} + 20$		ns

- Remarks**
1. $T = 1/f_{xx}$
 2. T_{smp} = Noise elimination sampling clock frequency

Reset



Interrupt



TIn Input Timing

($T_A = -40$ to $+85^\circ\text{C}$, $V_{DD} = AV_{DD} = BV_{DD} = 2.7$ to 3.6 V, $V_{SS} = AV_{SS} = BV_{SS} = 0$ V, $C_L = 50$ pF)

Parameter	Symbol		Conditions	MIN.	MAX.	Unit
Tl0n0, Tl0n1 (n = 0, 1) High-level width	t _{TIH}	<60>		2T _{sam} + 20 ^{Note}		ns
TIn (n = 2 to 7, 10, 11) High-level width				3T + 20		ns
Tl0n0, Tl0n1 (n = 0, 1) Low-level width	t _{TIL}	<61>		2T _{sam} + 20 ^{Note}		ns
TIn (n = 2 to 7, 10, 11) Low-level width				3T + 20		ns

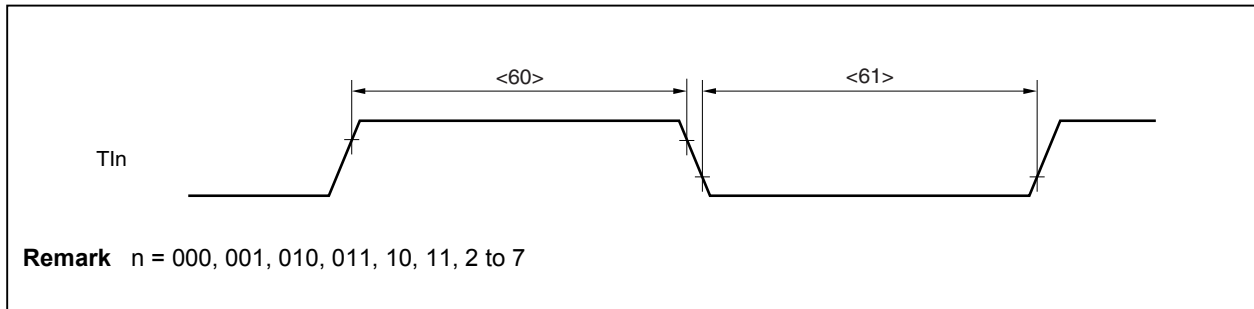
Note T_{sam} can be selected by setting the PRMn2 to PRMn0 bits of prescaler mode registers n0, n1 (PRMn0, PRMn1) (n = 0, 1).

TM0 (PRM00, PRM01 registers): T_{sam} = 2T, 4T, 16T, 64T, 256T, 1/INTW_{TN} period

TM1 (PRM10, PRM11 registers): T_{sam} = 2T, 4T, 16T, 32T, 128T, 256T

However, when the TIn0 valid edge is selected as the count clock, T_{sam} = 2T (n = 0, 1).

Remark T: 1/f_{xx}



3-Wire SIO Timing

(1) Master mode ($T_A = -40$ to $+85^\circ\text{C}$, $V_{DD} = AV_{DD} = BV_{DD} = 2.7$ to 3.6 V, $V_{SS} = AV_{SS} = BV_{SS} = 0$ V, $C_L = 50$ pF)

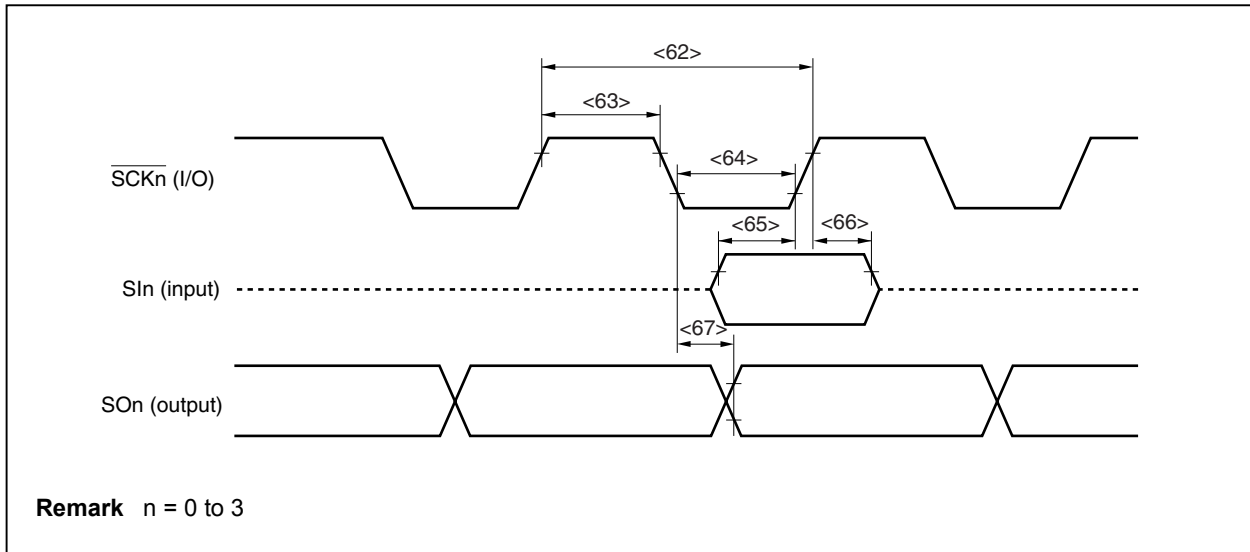
Parameter	Symbol	Conditions	MIN.	MAX.	Unit
$\overline{\text{SCKn}}$ cycle time	t_{KCY1}	<62>	400		ns
$\overline{\text{SCKn}}$ high-level width	t_{KH1}	<63>	140		ns
$\overline{\text{SCKn}}$ low-level width	t_{KL1}	<64>	140		ns
SIn setup time (to $\overline{\text{SCKn}}\uparrow$)	t_{SIK1}	<65>	50		ns
SIn hold time (from $\overline{\text{SCKn}}\downarrow$)	t_{KSI1}	<66>	50		ns
Delay time from $\overline{\text{SCKn}}\downarrow$ to SOn output	t_{KSO1}	<67>		60	ns

Remark n = 0 to 3

(2) Slave mode ($T_A = -40$ to $+85^\circ\text{C}$, $V_{DD} = AV_{DD} = BV_{DD} = 2.7$ to 3.6 V, $V_{SS} = AV_{SS} = BV_{SS} = 0$ V, $C_L = 50$ pF)

Parameter	Symbol	Conditions	MIN.	MAX.	Unit
$\overline{\text{SCKn}}$ cycle time	t_{KCY2}	<62>	400		ns
★ $\overline{\text{SCKn}}$ high-level width	t_{KH2}	<63>	180		ns
★ $\overline{\text{SCKn}}$ low-level width	t_{KL2}	<64>	180		ns
SIn setup time (to $\overline{\text{SCKn}}\uparrow$)	t_{SIK2}	<65>	50		ns
SIn hold time (from $\overline{\text{SCKn}}\downarrow$)	t_{KSI2}	<66>	50		ns
Delay time from $\overline{\text{SCKn}}\downarrow$ to SOn output	t_{KSO2}	<67>		60	ns

Remark n = 0 to 3



Remark n = 0 to 3

3-Wire Variable-Length CSI Timing

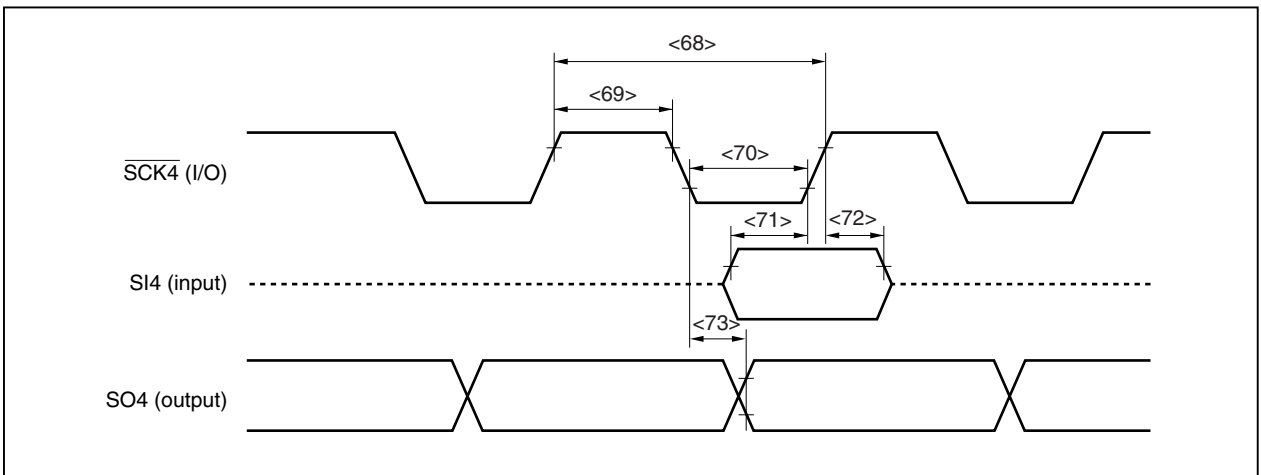
(1) Master mode ($T_A = -40$ to $+85^\circ\text{C}$, $V_{DD} = AV_{DD} = BV_{DD} = 2.7$ to 3.6 V, $V_{SS} = AV_{SS} = BV_{SS} = 0$ V, $C_L = 50$ pF)

Parameter	Symbol		Conditions	MIN.	MAX.	Unit
$\overline{\text{SCK4}}$ cycle time	t_{KCY1}	<68>		400		ns
$\overline{\text{SCK4}}$ high-level width	t_{KH1}	<69>		140		ns
$\overline{\text{SCK4}}$ low-level width	t_{KL1}	<70>		140		ns
SI4 setup time (to $\overline{\text{SCK4}}\uparrow$)	t_{SIK1}	<71>		50		ns
SI4 hold time (from $\overline{\text{SCK4}}\downarrow$)	t_{KSI1}	<72>		50		ns
Delay time from $\overline{\text{SCK4}}\downarrow$ to SO4 output	t_{KSO1}	<73>			60	ns

(2) Slave mode ($T_A = -40$ to $+85^\circ\text{C}$, $V_{DD} = AV_{DD} = BV_{DD} = 2.7$ to 3.6 V, $V_{SS} = AV_{SS} = BV_{SS} = 0$ V, $C_L = 50$ pF)

★
★

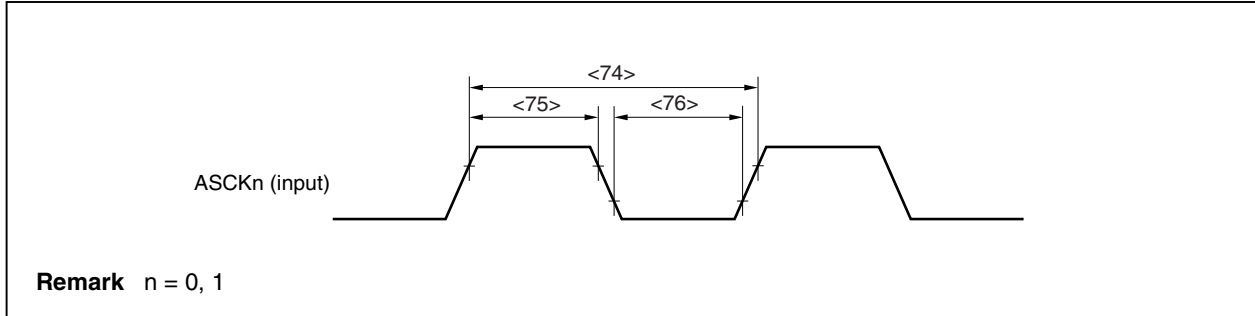
Parameter	Symbol		Conditions	MIN.	MAX.	Unit
$\overline{\text{SCK4}}$ cycle time	t_{KCY2}	<68>		400		ns
$\overline{\text{SCK4}}$ high-level width	t_{KH2}	<69>		180		ns
$\overline{\text{SCK4}}$ low-level width	t_{KL2}	<70>		180		ns
SI4 setup time (to $\overline{\text{SCK4}}\uparrow$)	t_{SIK2}	<71>		50		ns
SI4 hold time (from $\overline{\text{SCK4}}\downarrow$)	t_{KSI2}	<72>		50		ns
Delay time from $\overline{\text{SCK4}}\downarrow$ to SO4 output	t_{KSO2}	<73>			60	ns



UART Timing ($T_A = -40$ to $+85^\circ\text{C}$, $V_{DD} = AV_{DD} = BV_{DD} = 2.7$ to 3.6 V, $V_{SS} = AV_{SS} = BV_{SS} = 0$ V, $C_L = 50$ pF)

Parameter	Symbol	Conditions	MIN.	MAX.	Unit
ASCKn cycle time	t_{KCY13}	<74>	200		ns
ASCKn high-level width	t_{KH13}	<75>	80		ns
ASCKn low-level width	t_{KL13}	<76>	80		ns

Remark n = 0, 1



Remark n = 0, 1

I²C Bus Mode (Only for μ PD70F3038Y and 70F3040Y)

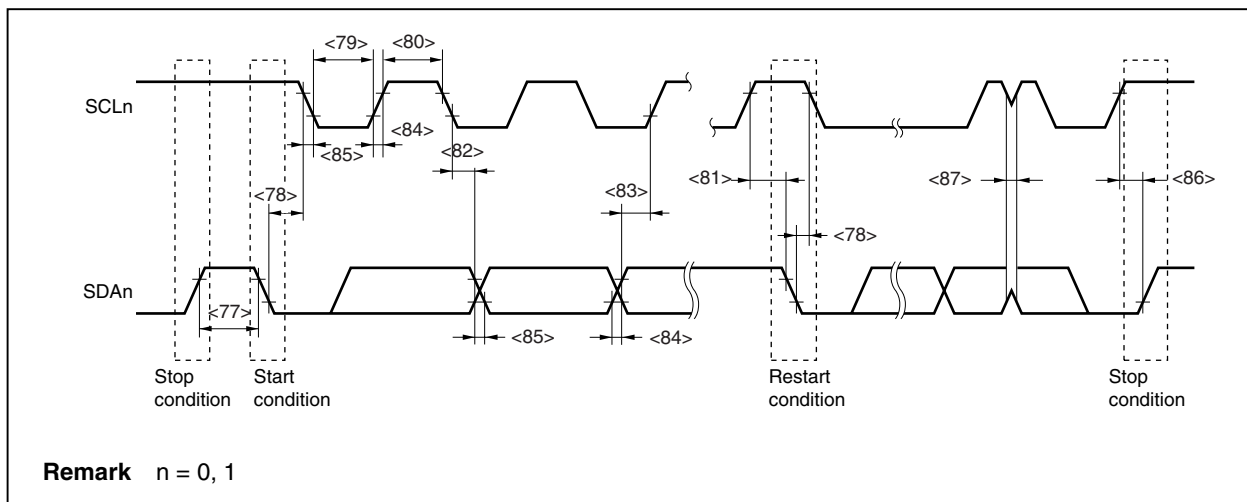
(T_A = -40 to +85°C, V_{DD} = AV_{DD} = BV_{DD} = 2.7 to 3.6 V, V_{SS} = AV_{SS} = BV_{SS} = 0 V, C_L = 50 pF)

Parameter		Symbol		Standard Mode		High-Speed Mode		Unit
				MIN.	MAX.	MIN.	MAX.	
SCLn clock frequency		f _{CLK}		0	100	0	400	kHz
Bus free time (between stop/start conditions)		t _{BUF}	<77>	4.7		1.3		μs
Hold time ^{Note 1}		t _{HD: STA}	<78>	4.0		0.6		μs
SCLn clock low-level width		t _{LOW}	<79>	4.7		1.3		μs
SCLn clock high-level width		t _{HIGH}	<80>	4.0		0.6		μs
Setup time of start/restart conditions		t _{SU: STA}	<81>	4.7		0.6		μs
Data hold time	CBUS-compatible master	t _{HD: DAT}	<82>	5.0				μs
	I ² C bus mode			0 ^{Note 2}		0 ^{Note 2}	0.9 ^{Note 3}	μs
Data setup time		t _{SU: DAT}	<83>	250		100 ^{Note 4}		ns
Rising time of SDAn and SCLn signals		t _R	<84>		1000	20 + 0.1Cb ^{Note 5}	300	ns
Falling time of SDAn and SCLn signals		t _F	<85>		300	20 + 0.1Cb ^{Note 5}	300	ns
Setup time of stop condition		t _{SU: STO}	<86>	4.0		0.6		μs
Pulse width of spike suppressed by input filter		t _{SP}	<87>			0	50	ns
Load capacitance of bus line		Cb			400		400	pF

- Notes 1.** The first clock pulse in the start condition is generated after the hold time.
- 2.** The system must internally provide at least 300 ns hold time for the SDAn signal (at V_{IHmin.} of the SCLn signal) in order to fill the undefined period that appears at the SCLn falling edge.
- 3.** If the system does not extend the low-state hold time (t_{LOW}), only the maximum data hold time (t_{HD: DAT}) has to be satisfied.
- 4.** The high-speed I²C bus is available in a standard mode I²C bus system. In this case, the following conditions should be satisfied.
- When the system does not extend the low-state hold time of the SCLn signal
t_{SU: DAT} ≥ 250 ns
 - When the system extends the low-state hold time of the SCLn signal
Send the next data bit to the SDAn line before the SCLn line is released (t_{Rmax.} + t_{SU: DAT} = 1000 + 250 = 1250 ns: Standard mode I²C bus specification).
- 5.** Cb: Total capacitance of one bus line (Unit: pF)

- Remarks 1.** n = 0, 1
- 2.** The maximum operating frequency of I²C is f_{xx} = 17 MHz.
However, when 16 MHz < f_{xx} ≤ 17 MHz, use the system with V_{DD} = 3.1 V to 3.6 V.

I²C Bus Mode (Only for μPD70F3038Y and 70F3040Y)



A/D Converter (T_A = -40 to +85°C, V_{DD} = AV_{DD} = AV_{REF} = 2.7 to 3.6 V, AV_{SS} = V_{SS} = 0 V, C_L = 50 pF)

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Resolution			10	10	10	bit
Overall error ^{Note 1}					±0.8	%FSR
Conversion time	t _{CONV}		5		100	μs
Zero-scale error ^{Note 1}					±0.4	%FSR
Full-scale error ^{Note 1}					±0.4	%FSR
Integral linearity error ^{Note 2}					±4.0	LSB
Differential linearity error ^{Note 2}					±4.0	LSB
Analog reference voltage	AV _{REF}	AV _{REF} = AV _{DD}	2.7		3.6	V
Analog input voltage	V _{IAN}		AV _{SS}		AV _{REF}	V
★ AV _{REF} current	AI _{REF}			360	500	μA
★ A/D converter supply current	AI _{DD}	During normal operation		1	3	mA
	AI _{DDS}	During STOP mode		1	10	μA

Notes 1. Excluding quantization error (±0.05%FSR)

2. Excluding quantization error (±0.5LSB)

Remark LSB: Least Significant Bit
FSR: Full Scale Range

★ Flash Memory Programming Mode

Basic Characteristics (TA = 10 to 40 °C, VDD = AVDD = BVDD = 3.0 to 3.6 V, VSS = AVSS = BVSS = 0 V)

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
V _{PP} supply voltage	V _{PP2}	In flash memory programming mode	7.5	7.8	8.1	V
V _{DD} supply current	I _{DD}	μPD70F3038, μPD70F3038Y f _{XX} = 16 MHz, V _{DD} = 3.0 to 3.6 V V _{PP} = V _{PP2}			66	mA
		f _{XX} = 20 MHz, V _{DD} = 3.1 to 3.6 V			72	mA
		μPD70F3040, μPD70F3040Y f _{XX} = 16 MHz, V _{DD} = 3.0 to 3.6 V V _{PP} = V _{PP2}			61	mA
		f _{XX} = 20 MHz, V _{DD} = 3.1 to 3.6 V			67	mA
V _{PP} supply voltage	I _{PP}	V _{PP} = V _{PP2}			200	mA
Step erase time	t _{ER}	Note 1		0.2		s
Total erase time per area	t _{ERA}	Step erase time = 0.2 s, Note 2			20	s/area
Writeback time	t _{WB}	Note 3		1		ms
Number of writebacks per writeback command	C _{WB}	Writeback time = 1 ms, Note 4			300	Times/ Writeback command
Number of erases – writebacks	C _{ERWB}				16	Time
Step write time	t _{WR}	Note 5		20		μs
Total write time per word	t _{WRW}	When step write time is set to 20 μs (1 word = 4 bytes), Note 6	20		200	μs/ word
Number of rewrites per area	C _{ERWR}	One erase + one write after erase = One rewrite, Note 7	20			Times/ area

- Notes**
- The recommended set value of the step erase time is 0.2 s.
 - The value does not include the prewrite and erase verify (writeback) time prior to erase.
 - The recommended set value of the writeback time is 1 ms.
 - Issuing a writeback command performs one writeback. Therefore, subtract the number of times a command is issued from this value to set the number of retries.
 - The recommended set value of the step write time is 20 μs.
 - The actual write time per word is the total of this value and 20 μs. It does not include the internal verify time during and after writing.
 - When a product is written for the first time, both erase → write and write only is considered as one rewrite.

Example (P: Write, E: Erase)

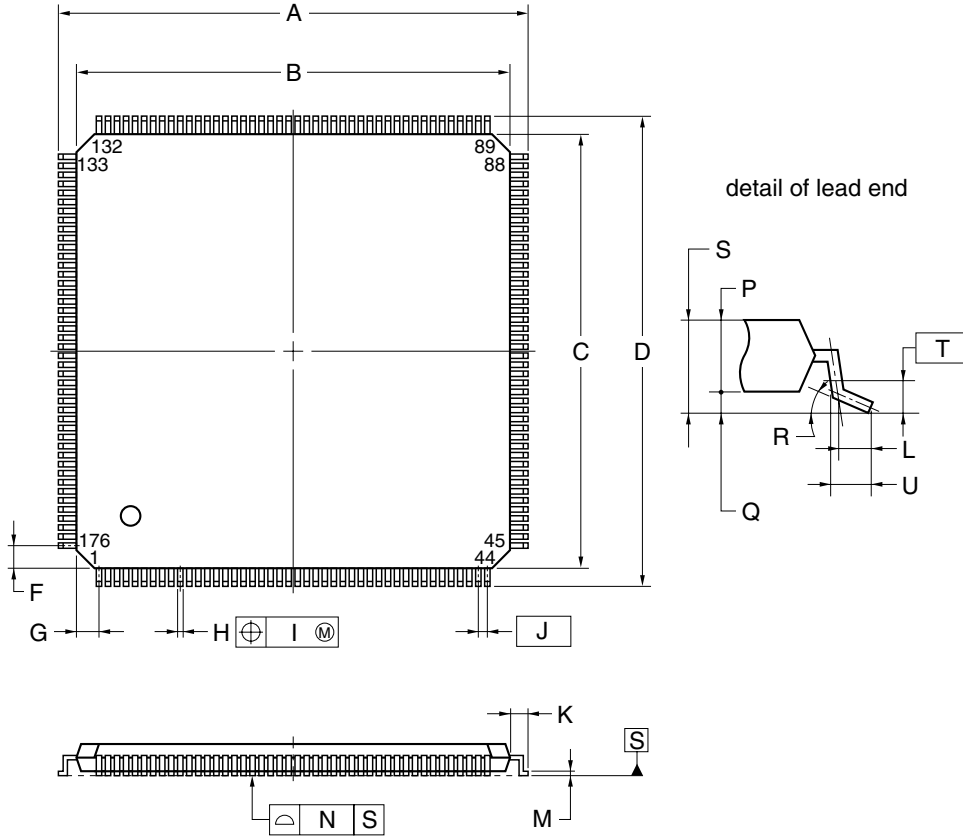
Product → P → E → P → E → P: 3 rewrites

Product → E → P → E → P → E → P: 3 rewrites

- Remarks**
- The operation clock range in the flash memory programming mode is the same as that during normal operation.
 - When the PG-FP3 is used, time parameters required for write/erase are automatically set by downloading a parameter file. Unless otherwise specified, do not change the set values.
 - Area 0 = 00000H to 1FFFFH, area 1 = 20000H to 3FFFFH, area 2 = 040000 to 05FFFFH (μPD70F3038, 70F3038Y)
Area 0 = 00000H to 1FFFFH, area 1 = 20000H to 3FFFFH (μPD70F3040, 70F3040Y)

3. PACKAGE DRAWING

176-PIN PLASTIC LQFP (FINE PITCH) (24x24)



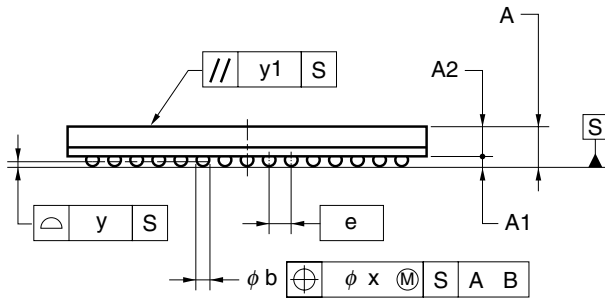
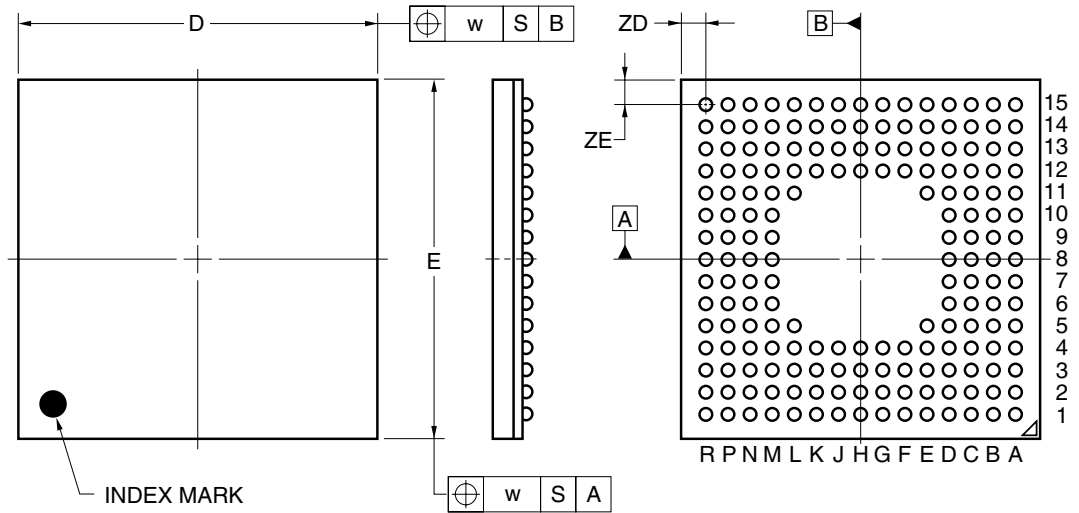
NOTE

Each lead centerline is located within 0.10 mm of its true position (T.P.) at maximum material condition.

ITEM	MILLIMETERS
A	26.0±0.2
B	24.0±0.2
C	24.0±0.2
D	26.0±0.2
F	1.25
G	1.25
H	0.22±0.05
I	0.08
J	0.5 (T.P.)
K	1.0±0.2
L	0.5
M	0.17 ^{+0.03} _{-0.07}
N	0.08
P	1.4
Q	0.1±0.05
R	3° ^{+4°} _{-3°}
S	1.5±0.1
T	0.25
U	0.60±0.15

S176GM-50-UEU-1

★ 180-PIN PLASTIC FBGA (13x13)



ITEM	MILLIMETERS
D	13.00±0.10
E	13.00±0.10
w	0.2
A	1.48±0.10
A1	0.35±0.06
A2	1.13
e	0.80
b	0.50±0.05
x	0.08
y	0.10
y1	0.20
ZD	0.90
ZE	0.90

P180F1-80-EN2

★ 4. RECOMMENDED SOLDERING CONDITIONS

The μPD70F3038, 70F3038Y, 70F3040, and 70F3040Y should be soldered and mounted under the following recommended conditions.

For details of the recommended soldering conditions, refer to the document **Semiconductor Device Mounting Technology Manual (C10535E)**.

For soldering methods and conditions other than those recommended below, contact an NEC sales representative.

Table 4-1. Surface Mounting Type Soldering Conditions

(a) μPD70F3040GM-xxx-UEU: 176-pin plastic LQFP (fine pitch) (24 × 24)

μPD70F3040YGM-xxx-UEU: 176-pin plastic LQFP (fine pitch) (24 × 24)

Soldering Method	Soldering Conditions	Recommended Condition Symbol
Infrared reflow	Package peak temperature: 235°C, Time: 30 seconds max. (at 210°C or higher), Count: Twice or less, Exposure limit: 3 days ^{Note} (after that, prebake at 125°C for 10 hours)	IR35-103-2
VPS	Package peak temperature: 215°C, Time: 25 to 40 seconds (at 200°C or higher), Count: Twice or less, Exposure limit: 3 days ^{Note} (after that, prebake at 125°C for 10 hours)	VP15-103-2
Partial heating	Pin temperature: 300°C max., Time 3 seconds max. (per pin row)	—

Note After opening the dry pack, store it at 25°C or less and 65% RH or less for the allowable storage period.

Caution Do not use different soldering methods together (except for partial heating).

- (b) μ PD70F3038F1-EN2: 180-pin plastic FBGA (13 × 13)
- μ PD70F3038YF1-EN2: 180-pin plastic FBGA (13 × 13)
- μ PD70F3040F1-EN2: 180-pin plastic FBGA (13 × 13)
- μ PD70F3040YF1-EN2: 180-pin plastic FBGA (13 × 13)

Soldering Method	Soldering Conditions	Recommended Condition Symbol
Infrared reflow	Package peak temperature: 235°C, Time: 30 seconds max. (at 210°C or higher), Count: Twice or less, Exposure limit: 7 days ^{Note} (after that, prebake at 125°C for 10 hours)	IR35-107-2
VPS	Package peak temperature: 215°C, Time: 25 to 40 seconds (at 200°C or higher), Count: Twice or less, Exposure limit: 7 days ^{Note} (after that, prebake at 125°C for 10 hours)	VP15-107-2
Partial heating	Pin temperature: 300°C max., Time 3 seconds max. (per pin row)	—

Note After opening the dry pack, store it at 25°C or less and 65% RH or less for the allowable storage period.

Caution Do not use different soldering methods together (except for partial heating).

[MEMO]

[MEMO]

NOTES FOR CMOS DEVICES

① PRECAUTION AGAINST ESD FOR SEMICONDUCTORS

Note:

Strong electric field, when exposed to a MOS device, can cause destruction of the gate oxide and ultimately degrade the device operation. Steps must be taken to stop generation of static electricity as much as possible, and quickly dissipate it once, when it has occurred. Environmental control must be adequate. When it is dry, humidifier should be used. It is recommended to avoid using insulators that easily build static electricity. Semiconductor devices must be stored and transported in an anti-static container, static shielding bag or conductive material. All test and measurement tools including work bench and floor should be grounded. The operator should be grounded using wrist strap. Semiconductor devices must not be touched with bare hands. Similar precautions need to be taken for PW boards with semiconductor devices on it.

② HANDLING OF UNUSED INPUT PINS FOR CMOS

Note:

No connection for CMOS device inputs can be cause of malfunction. If no connection is provided to the input pins, it is possible that an internal input level may be generated due to noise, etc., hence causing malfunction. CMOS devices behave differently than Bipolar or NMOS devices. Input levels of CMOS devices must be fixed high or low by using a pull-up or pull-down circuitry. Each unused pin should be connected to V_{DD} or GND with a resistor, if it is considered to have a possibility of being an output pin. All handling related to the unused pins must be judged device by device and related specifications governing the devices.

③ STATUS BEFORE INITIALIZATION OF MOS DEVICES

Note:

Power-on does not necessarily define initial status of MOS device. Production process of MOS does not define the initial operation status of the device. Immediately after the power source is turned ON, the devices with reset function have not yet been initialized. Hence, power-on does not guarantee out-pin levels, I/O settings or contents of registers. Device is not initialized until the reset signal is received. Reset operation must be executed immediately after power-on for devices having reset function.

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Related document μ PD703038, 703038Y, 703039, 703039Y, 703040, 703040Y, 703041, 703041Y Data Sheet (U13953E)

Reference document Electrical Characteristics for Microcomputer (U15170J) ^{Note}

Note This document number is that of the Japanese version.

The documents indicated in this publication may include preliminary versions. However, preliminary versions are not marked as such.

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